LAMPIRAN 1

```
#include<LiquidCrystal.h>
#include <Wire.h>
#include <TimeLib.h>
#include <DS1307RTC.h>
#include <TimeAlarms.h>
LiquidCrystal lcd(2, 3, 4, 5, 6, 7);

#define PWM_MOTOR_1 8
#define MOTOR_A1_PIN 9
#define MOTOR_B1_PIN 10
boolean kondisi = true;
tmElements_t tm;

void setup() {
 Serial.begin(9600);
 lcd.begin(16, 2);
 pinMode(MOTOR_A1_PIN, OUTPUT);
 pinMode(MOTOR_B1_PIN, OUTPUT);
 pinMode(PWM_MOTOR_1, OUTPUT);
 digitalWrite (PWM_MOTOR_1, HIGH);

 // Tentukan alarm
 RTC.read(tm);
 setTime(tm.Hour, tm.Minute, tm.Second, tm.Day, tm.Month,
tmYearToCalendar(tm.Year));
 Alarm.alarmRepeat(16, 40, 00, motorAlarm);
```

```
}



void motorBergerak()
{
 if (kondisi == true)
 {
  digitalWrite (MOTOR_A1_PIN, HIGH);
  digitalWrite (MOTOR_B1_PIN, LOW);
 }
 kondisi = false;
 return kondisi;
}


void motorDiam()
{
 if (kondisi == false)
 {
  digitalWrite (MOTOR_A1_PIN, LOW);
  digitalWrite (MOTOR_B1_PIN, LOW);
 }
 kondisi = true;
 return kondisi;
}
void motorAlarm()
{
```

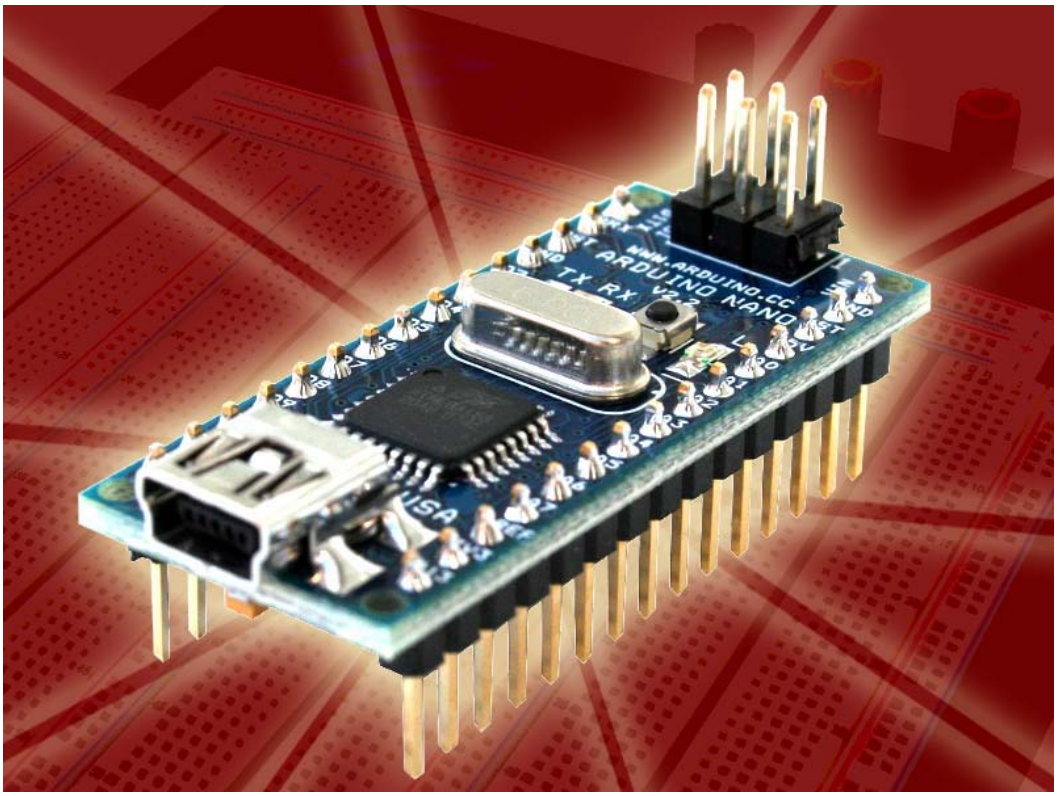
```
 lcd.clear();
 lcd.setCursor(0, 0);
 lcd.print("Motor bergerak");
 motorBergerak();
 delay(3000);
 motorDiam();
 lcd.clear();
}

void tampilkanJam()
{
 RTC.read(tm);
 lcd.setCursor(0, 0);
 lcd.print("Time");
 lcd.setCursor(5, 0);
 lcd.print('=');
 lcd.setCursor(7, 0);
 print2digits(tm.Hour);
 lcd.setCursor(9, 0);
 lcd.print(':');
 lcd.setCursor(10, 0);
 print2digits(tm.Minute);
 lcd.setCursor(12, 0);
 lcd.print(':');
 lcd.setCursor(13, 0);
 print2digits(tm.Second);
```

```
  lcd.setCursor(0, 1);
  lcd.print("Date");
  lcd.setCursor(5, 1);
  lcd.print('=');
  lcd.setCursor(6, 1);
  print2digits(tm.Day);
  lcd.setCursor(8, 1);
  lcd.print('/');
  lcd.setCursor(9, 1);
  print2digits(tm.Month);
  lcd.setCursor(11, 1);
  lcd.print('/');
  lcd.setCursor(12, 1);
  print2digits(tmYearToCalendar(tm.Year));
}
void print2digits(int number) {
  if (number >= 0 && number < 10) {
    lcd.print('0');
  }
  lcd.print(number);
}
void loop() {
  tampilkanJam();
  Alarm.delay(1000);
}
```

LAMPIRAN 2

Arduino Nano (V2.3)

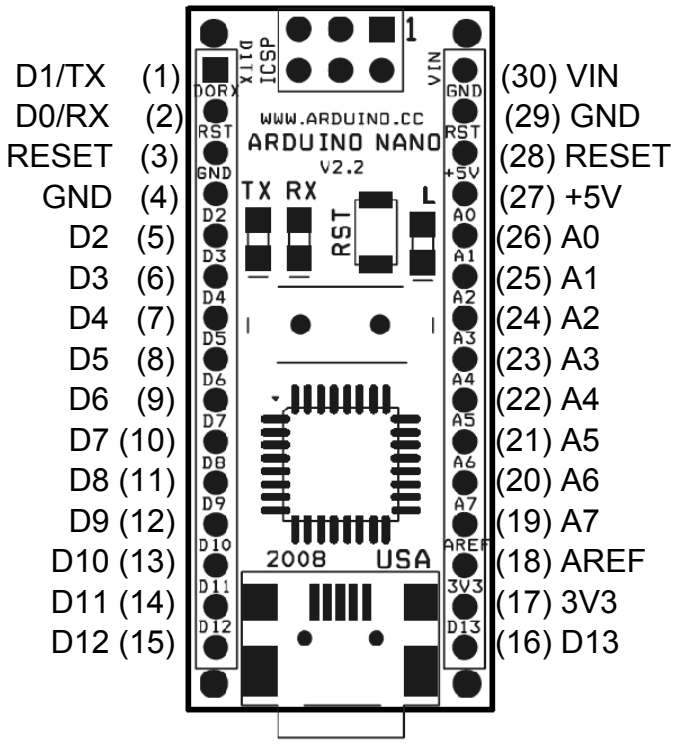
User Manual



More information:

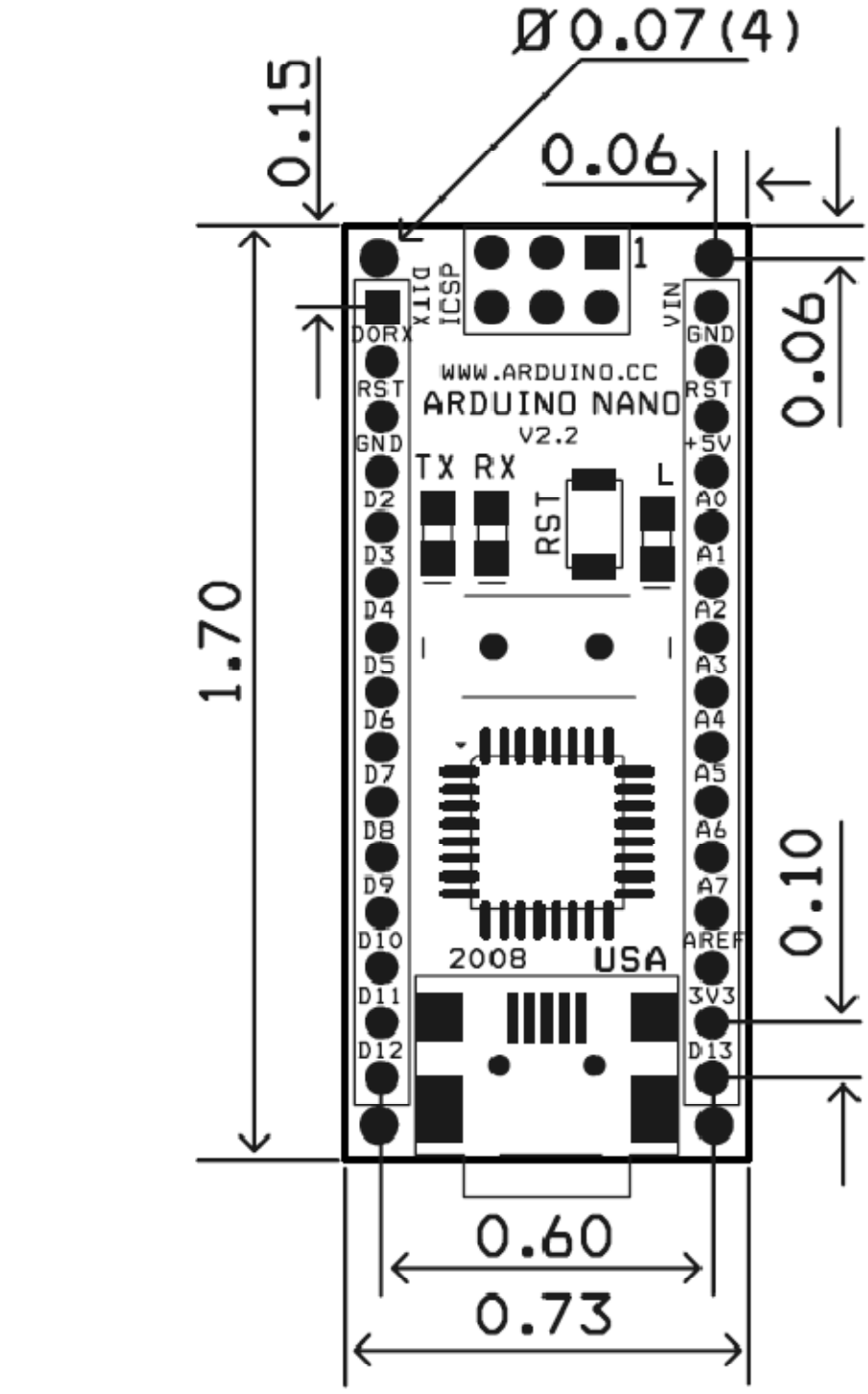
www.arduino.cc Rev. 2.3

Arduino Nano Pin Layout



Pin No.	Name	Type	Description
1-2, 5-16	D0-D13	I/O	Digital input/output port 0 to 13
3, 28	RESET	Input	Reset (active low)
4, 29	GND	PWR	Supply ground
17	3V3	Output	+3.3V output (from FTDI)
18	AREF	Input	ADC reference
19-26	A7-A0	Input	Analog input channel 0 to 7
27	+5V	Output or Input	+5V output (from on-board regulator) or +5V (input from external power supply)
30	VIN	PWR	Supply voltage

Arduino Nano Mechanical Drawing

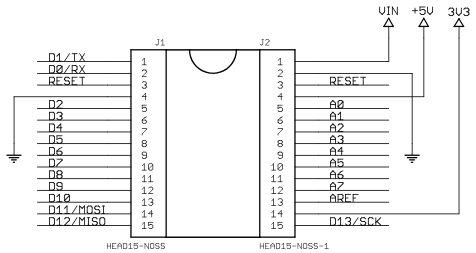


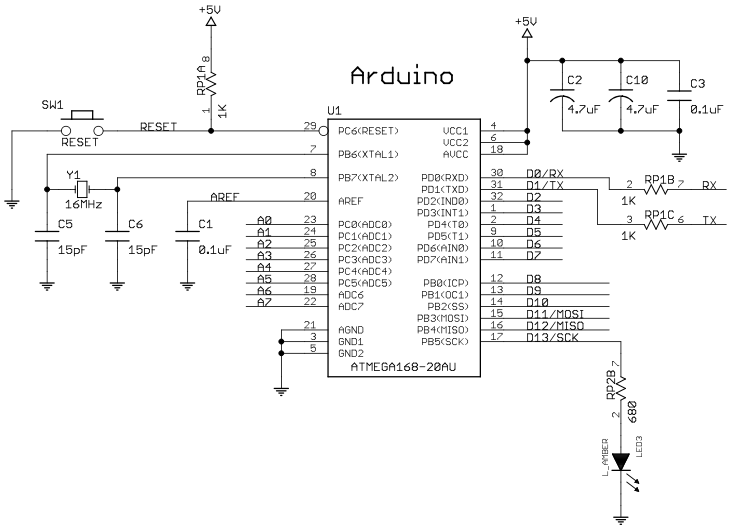
ALL DIMENTIONS ARE IN INCHES

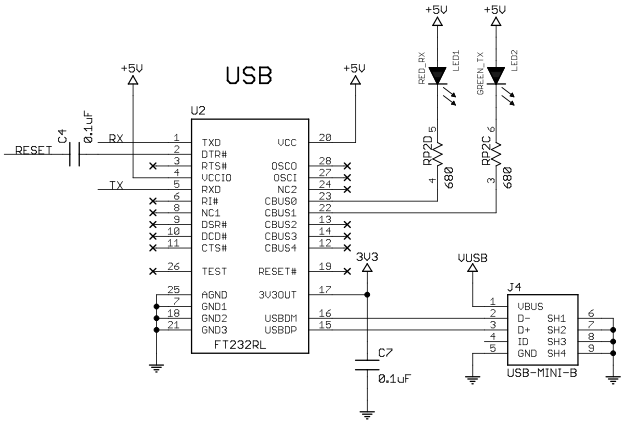
Arduino Nano Bill of Material

Item Number	Qty.	Ref. Dest.	Description	Mfg. P/N	MFG	Vendor P/N	Vendor
1	5	C1,C3,C4,C7,C9	Capacitor, 0.1uF 50V 10% Ceramic X7R 0805	C0805C104K5RACTU	Kemet	80-C0805C104K5R	Mouser
2	3	C2,C8,C10	Capacitor, 4.7uF 10V 10% Tantalum Case A	T491A475K010AT	Kemet	80-T491A475K010	Mouser
3	2	C5,C6	Capacitor, 18pF 50V 5% Ceramic NOP/COG 0805	C0805C180J5GACTU	Kemet	80-C0805C180J5G	Mouser
4	1	D1	Diode, Schottky 0.5A 20V	MBR0520LT1G	ONSemi	863-MBR0520LT1G	Mouser
5	1	J1,J2	Headers, 36PS 1 Row	68000-136HLF	FCI	649-68000-136HLF	Mouser
6	1	J4	Connector, Mini-B Recept Rt. Angle	67503-1020	Molex	538-67503-1020	Mouser
7	1	J5	Headers, 72PS 2 Rows	67996-272HLF	FCI	649-67996-272HLF	Mouser
8	1	LD1	LED, Super Bright RED 100mcd 640nm 120degree 0805	APT2012SRCPRV	Kingbright	604-APT2012SRCPRV	Mouser
9	1	LD2	LED, Super Bright GREEN 50mcd 570nm 110degree 0805	APHCM2012CGCK-F01	Kingbright	604-APHCM2012CGCK	Mouser
10	1	LD3	LED, Super Bright ORANGE 160mcd 601nm 110degree 0805	APHCM2012SECK-F01	Kingbright	04-APHCM2012SECK	Mouser
11	1	LD4	LED, Super Bright BLUE 80mcd 470nm 110degree 0805	LTST-C170TBKT	Lite-On Inc	160-1579-1-ND	Digikey
12	1	R1	Resistor Pack, 1K +/-5% 62.5mW 4RES SMD	YC164-JR-071KL	Yageo	YC164J-1.0KCT-ND	Digikey
13	1	R2	Resistor Pack, 680 +/-5% 62.5mW 4RES SMD	YC164-JR-07680RL	Yageo	YC164J-680CT-ND	Digikey
14	1	SW1	Switch, Momentary Tact SPST 150gf 3.0x2.5mm	B3U-1000P	Omron	SW1020CT-ND	Digikey
15	1	U1	IC, Microcontroller RISC 16kB Flash, 0.5kB EEPROM, 23 I/O Pins	ATmega168-20AU	Atmel	556-ATMEGA168-20AU	Mouser
16	1	U2	IC, USB to SERIAL UART 28 Pins SSOP	FT232RL	FTDI	895-FT232RL	Mouser
17	1	U3	IC, Voltage regulator 5V, 500mA SOT-223	UA78M05CDCYRG3	TI	595-UA78M05CDCYRG3	Mouser
18	1	Y1	Cystal, 16MHz +/-20ppm HC-49/US Low Profile	ABL-16.000MHZ-B2	Abracon	815-ABL-16-B2	Mouser

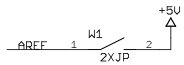
Arduino Nano Schematic



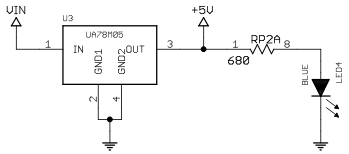




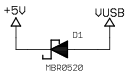
+5V AREF OPTION



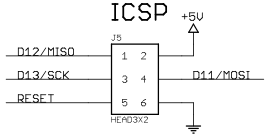
+5V REG



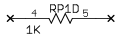
+5V AUTO SELECTOR

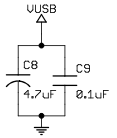


ICSP



NOT USED





v2.3 - Modify FT232RL to use +5V	
TITLE: Arduino Nano	
Document Number:	REV: 2.3
Date: 6/26/2008 8:35:54 PM	Sheet: 1/1

LAMPIRAN 3

DS3231

Extremely Accurate I²C-Integrated RTC/TCXO/Crystal

General Description

The DS3231 is a low-cost, extremely accurate I²C real-time clock (RTC) with an integrated temperature-compensated crystal oscillator (TCXO) and crystal. The device incorporates a battery input, and maintains accurate timekeeping when main power to the device is interrupted. The integration of the crystal resonator enhances the long-term accuracy of the device as well as reduces the piece-part count in a manufacturing line. The DS3231 is available in commercial and industrial temperature ranges, and is offered in a 16-pin, 300-mil SO package.

The RTC maintains seconds, minutes, hours, day, date, month, and year information. The date at the end of the month is automatically adjusted for months with fewer than 31 days, including corrections for leap year. The clock operates in either the 24-hour or 12-hour format with an $\overline{\text{AM}}$/PM indicator. Two programmable time-of-day alarms and a programmable square-wave output are provided. Address and data are transferred serially through an I²C bidirectional bus.

A precision temperature-compensated voltage reference and comparator circuit monitors the status of V_{CC} to detect power failures, to provide a reset output, and to automatically switch to the backup supply when necessary. Additionally, the $\overline{\text{RST}}$ pin is monitored as a pushbutton input for generating a µP reset.

Benefits and Features

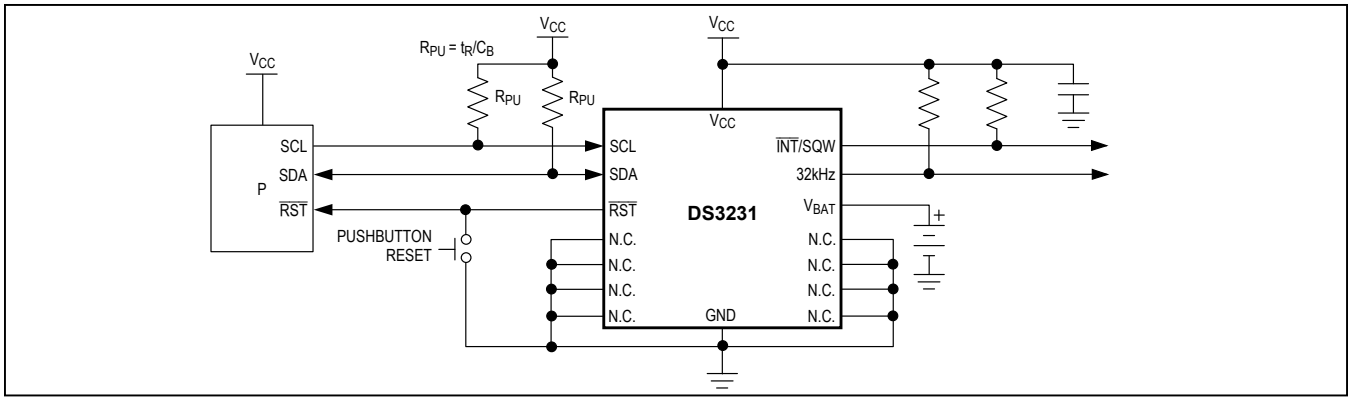
- Highly Accurate RTC Completely Manages All Timekeeping Functions
  - Real-Time Clock Counts Seconds, Minutes, Hours, Date of the Month, Month, Day of the Week, and Year, with Leap-Year Compensation Valid Up to 2100
  - Accuracy ±2ppm from 0°C to +40°C
  - Accuracy ±3.5ppm from -40°C to +85°C
  - Digital Temp Sensor Output: ±3°C Accuracy
  - Register for Aging Trim
  - $\overline{\text{RST}}$ Output/Pushbutton Reset Debounce Input
  - Two Time-of-Day Alarms
  - Programmable Square-Wave Output Signal
- Simple Serial Interface Connects to Most Microcontrollers
  - Fast (400kHz) I²C Interface
- Battery-Backup Input for Continuous Timekeeping
  - Low Power Operation Extends Battery-Backup Run Time
  - 3.3V Operation
- Operating Temperature Ranges: Commercial (0°C to +70°C) and Industrial (-40°C to +85°C)
- Underwriters Laboratories® (UL) Recognized

Applications

- Servers
- Telematics
- Utility Power Meters
- GPS

Ordering Information and Pin Configuration appear at end of data sheet.

Typical Operating Circuit



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maxim integrated™

Absolute Maximum Ratings

Voltage Range on Any Pin Relative to Ground ....-0.3V to +6.0V
Junction-to-Ambient Thermal Resistance (θ_{JA}) (Note 1)73°C/W
Junction-to-Case Thermal Resistance (θ_{JC}) (Note 1) ....23°C/W
Operating Temperature Range
DS3231S .....0°C to +70°C
DS3231SN..... -40°C to +85°C
Junction Temperature.....+125°C
Storage Temperature Range..... -40°C to +85°C
Lead Temperature (soldering, 10s) .....+260°C
Soldering Temperature (reflow, 2 times max) .....+260°C
(see the *Handling*, *PCB Layout*, *and Assembly* section)

Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to **www.maximintegrated.com/thermal-tutorial**.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions

(T_A = T_{MIN} to T_{MAX}, unless otherwise noted.) (Notes 2, 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Supply Voltage	V_{CC}		2.3	3.3	5.5	V
	V_{BAT}		2.3	3.0	5.5	V
Logic 1 Input SDA, SCL	V_{IH}		0.7 x V_{CC}		V_{CC} + 0.3	V
Logic 0 Input SDA, SCL	V_{IL}		-0.3		0.3 x V_{CC}	V

Electrical Characteristics

(V_{CC} = 2.3V to 5.5V, V_{CC} = Active Supply (see Table 1), T_A = T_{MIN} to T_{MAX}, unless otherwise noted.) (Typical values are at V_{CC} = 3.3V, V_{BAT} = 3.0V, and T_A = +25°C, unless otherwise noted.) (Notes 2, 3)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Active Supply Current	I_{CCA}	(Notes 4, 5)	V_{CC} = 3.63V			200	µA
			V_{CC} = 5.5V			300	
Standby Supply Current	I_{CCS}	I²C bus inactive, 32kHz output on, SQW output off (Note 5)	V_{CC} = 3.63V			110	µA
			V_{CC} = 5.5V			170	
Temperature Conversion Current	$I_{CCSCONV}$	I²C bus inactive, 32kHz output on, SQW output off	V_{CC} = 3.63V			575	µA
			V_{CC} = 5.5V			650	
Power-Fail Voltage	V_{PF}			2.45	2.575	2.70	V
Logic 0 Output, 32kHz, $\overline{INT}$/SQW, SDA	V_{OL}	I_{OL} = 3mA				0.4	V
Logic 0 Output, $\overline{RST}$	V_{OL}	I_{OL} = 1mA				0.4	V
Output Leakage Current 32kHz, $\overline{INT}$/SQW, SDA	I_{LO}	Output high impedance		-1	0	+1	µA
Input Leakage SCL	I_{LI}			-1		+1	µA
$\overline{RST}$ Pin I/O Leakage	I_{OL}	$\overline{RST}$ high impedance (Note 6)		-200		+10	µA
V_{BAT} Leakage Current (V_{CC} Active)	I_{BATLKG}				25	100	nA

Electrical Characteristics (continued)

(V_{CC} = 2.3V to 5.5V, V_{CC} = Active Supply (see Table 1), T_A = T_{MIN} to T_{MAX}, unless otherwise noted.) (Typical values are at V_{CC} = 3.3V, V_{BAT} = 3.0V, and T_A = +25°C, unless otherwise noted.) (Notes 2, 3)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Output Frequency	f_{OUT}	V_{CC} = 3.3V or V_{BAT} = 3.3V			32.768		kHz
Frequency Stability vs. Temperature (Commercial)	$\Delta f/f_{OUT}$	V_{CC} = 3.3V or V_{BAT} = 3.3V, aging offset = 00h	0°C to +40°C			±2	ppm
			>40°C to +70°C			±3.5	
Frequency Stability vs. Temperature (Industrial)	$\Delta f/f_{OUT}$	V_{CC} = 3.3V or V_{BAT} = 3.3V, aging offset = 00h	-40°C to <0°C			±3.5	ppm
			0°C to +40°C			±2	
			>40°C to +85°C			±3.5	
Frequency Stability vs. Voltage	Δf/V				1		ppm/V
Trim Register Frequency Sensitivity per LSB	Δf/LSB	Specified at:	-40°C		0.7		ppm
			+25°C		0.1		
			+70°C		0.4		
			+85°C		0.8		
Temperature Accuracy	Temp	V_{CC} = 3.3V or V_{BAT} = 3.3V		-3		+3	°C
Crystal Aging	$\Delta f/f_O$	After reflow, not production tested	First year		±1.0		ppm
			0–10 years		±5.0		

Electrical Characteristics

(**V_{CC} = 0V, V_{BAT} = 2.3V to 5.5V**, T_A = T_{MIN} to T_{MAX}, unless otherwise noted.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Active Battery Current	I_{BATA}	$\overline{EOSC}$ = 0, BBSQW = 0, SCL = 400kHz (Note 5)	V_{BAT} = 3.63V			70	µA
			V_{BAT} = 5.5V			150	
Timekeeping Battery Current	I_{BATT}	$\overline{EOSC}$ = 0, BBSQW = 0, EN32kHz = 1, SCL = SDA = 0V or SCL = SDA = V_{BAT} (Note 5)	V_{BAT} = 3.63V		0.84	3.0	µA
			V_{BAT} = 5.5V		1.0	3.5	
Temperature Conversion Current	I_{BATTC}	$\overline{EOSC}$ = 0, BBSQW = 0, SCL = SDA = 0V or SCL = SDA = V_{BAT}	V_{BAT} = 3.63V			575	µA
			V_{BAT} = 5.5V			650	
Data-Retention Current	I_{BATTDR}	$\overline{EOSC}$ = 1, SCL = SDA = 0V, +25°C				100	nA

AC Electrical Characteristics

(V_{CC} = $V_{CC(MIN)}$ to $V_{CC(MAX)}$ or V_{BAT} = $V_{BAT(MIN)}$ to $V_{BAT(MAX)}$, V_{BAT} > V_{CC}, T_A = T_{MIN} to T_{MAX}, unless otherwise noted.) (Note 2)

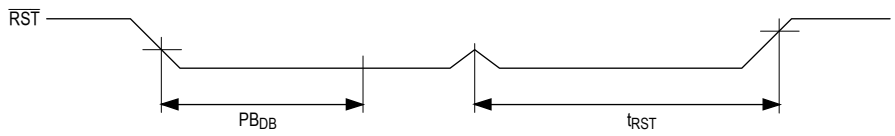
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
SCL Clock Frequency	f_{SCL}	Fast mode	100		400	kHz
		Standard mode	0		100	
Bus Free Time Between STOP and START Conditions	t_{BUF}	Fast mode	1.3			µs
		Standard mode	4.7			
Hold Time (Repeated) START Condition (Note 7)	$t_{HD:STA}$	Fast mode	0.6			µs
		Standard mode	4.0			
Low Period of SCL Clock	t_{LOW}	Fast mode	1.3			µs
		Standard mode	4.7			
High Period of SCL Clock	t_{HIGH}	Fast mode	0.6			µs
		Standard mode	4.0			
Data Hold Time (Notes 8, 9)	$t_{HD:DAT}$	Fast mode	0		0.9	µs
		Standard mode	0		0.9	
Data Setup Time (Note 10)	$t_{SU:DAT}$	Fast mode	100			ns
		Standard mode	250			
START Setup Time	$t_{SU:STA}$	Fast mode	0.6			µs
		Standard mode	4.7			
Rise Time of Both SDA and SCL Signals (Note 11)	t_R	Fast mode	20 + 0.1C_B		300	ns
		Standard mode			1000	
Fall Time of Both SDA and SCL Signals (Note 11)	t_F	Fast mode	20 + 0.1C_B		300	ns
		Standard mode			300	
Setup Time for STOP Condition	$t_{SU:STO}$	Fast mode	0.6			µs
		Standard mode	4.7			
Capacitive Load for Each Bus Line	C_B	(Note 11)			400	pF
Capacitance for SDA, SCL	$C_{I/O}$			10		pF
Pulse Width of Spikes That Must Be Suppressed by the Input Filter	t_{SP}			30		ns
Pushbutton Debounce	PB_{DB}			250		ms
Reset Active Time	t_{RST}			250		ms
Oscillator Stop Flag (OSF) Delay	t_{OSF}	(Note 12)		100		ms
Temperature Conversion Time	t_{CONV}			125	200	ms

Power-Switch Characteristics

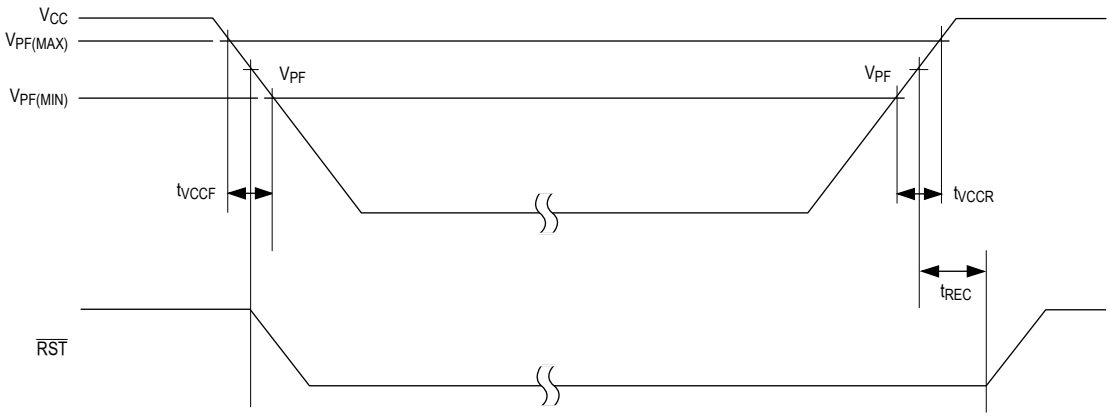
(T_A = T_{MIN} to T_{MAX})

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
V_{CC} Fall Time; $V_{PF(MAX)}$ to $V_{PF(MIN)}$	t_{VCCF}		300			µs
V_{CC} Rise Time; $V_{PF(MIN)}$ to $V_{PF(MAX)}$	t_{VCCR}		0			µs
Recovery at Power-Up	t_{REC}	(Note 13)		250	300	ms

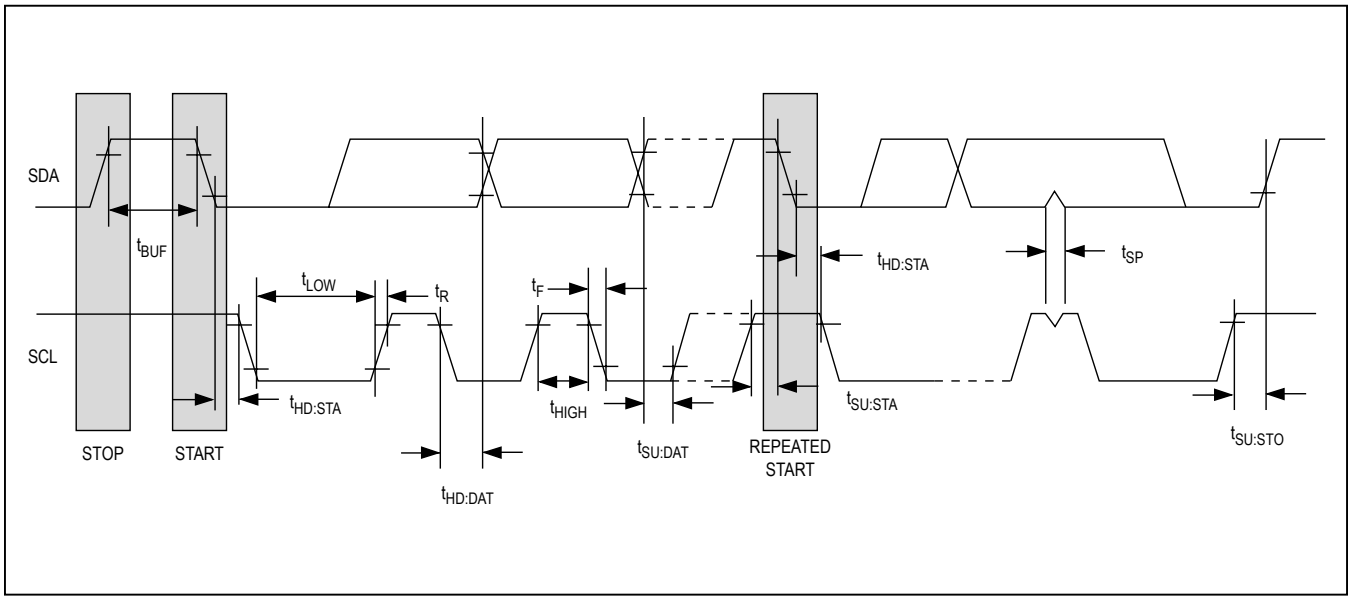
Pushbutton Reset Timing



Power-Switch Timing



Data Transfer on I2C Serial Bus



WARNING: Negative undershoots below -0.3V while the part is in battery-backed mode may cause loss of data.

Note 2: Limits at -40°C are guaranteed by design and not production tested.

Note 3: All voltages are referenced to ground.

Note 4: I_{CCA}—SCL clocking at max frequency = 400kHz.

Note 5: Current is the averaged input current, which includes the temperature conversion current.

Note 6: The $\overline{RST}$ pin has an internal 50kΩ (nominal) pullup resistor to V_{CC}.

Note 7: After this period, the first clock pulse is generated.

Note 8: A device must internally provide a hold time of at least 300ns for the SDA signal (referred to the $V_{IH(MIN)}$ of the SCL signal) to bridge the undefined region of the falling edge of SCL.

Note 9: The maximum $t_{HD:DAT}$ needs only to be met if the device does not stretch the low period (t_{LOW}) of the SCL signal.

Note 10: A fast-mode device can be used in a standard-mode system, but the requirement $t_{SU:DAT} \geq 250ns$ must then be met. This is automatically the case if the device does not stretch the low period of the SCL signal. If such a device does stretch the low period of the SCL signal, it must output the next data bit to the SDA line $t_{R(MAX)} + t_{SU:DAT} = 1000 + 250 = 1250ns$ before the SCL line is released.

Note 11: C_B—total capacitance of one bus line in pF.

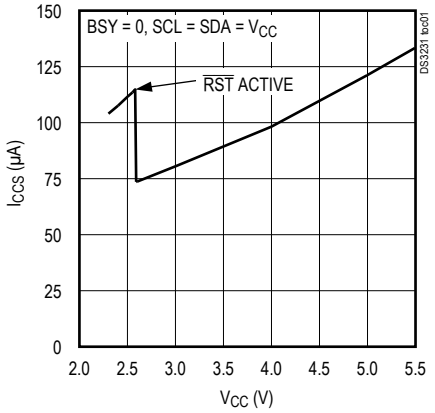
Note 12: The parameter t_{OSF} is the period of time the oscillator must be stopped for the OSF flag to be set over the voltage range of $0.0V \leq V_{CC} \leq V_{CC(MAX)}$ and $2.3V \leq V_{BAT} \leq 3.4V$.

Note 13: This delay applies only if the oscillator is enabled and running. If the $\overline{EOSC}$ bit is a 1, t_{REC} is bypassed and $\overline{RST}$ immediately goes high. The state of $\overline{RST}$ does not affect the I2C interface, RTC, or TCXO.

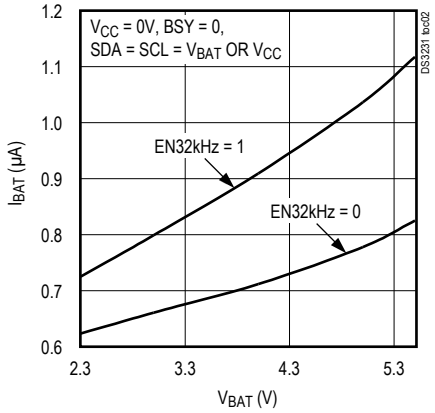
Typical Operating Characteristics

(V_{CC} = +3.3V, T_A = +25°C, unless otherwise noted.)

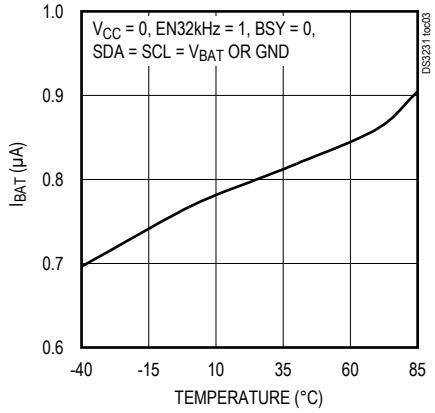
STANDBY SUPPLY CURRENT vs. SUPPLY VOLTAGE



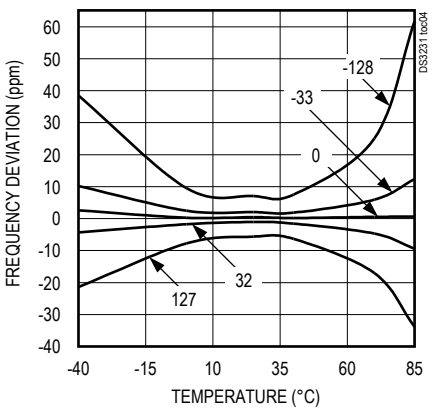
SUPPLY CURRENT vs. SUPPLY VOLTAGE



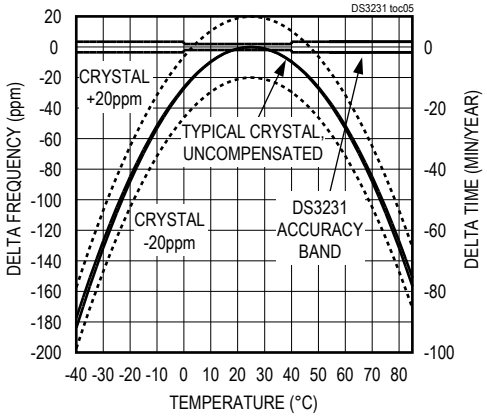
SUPPLY CURRENT vs. TEMPERATURE



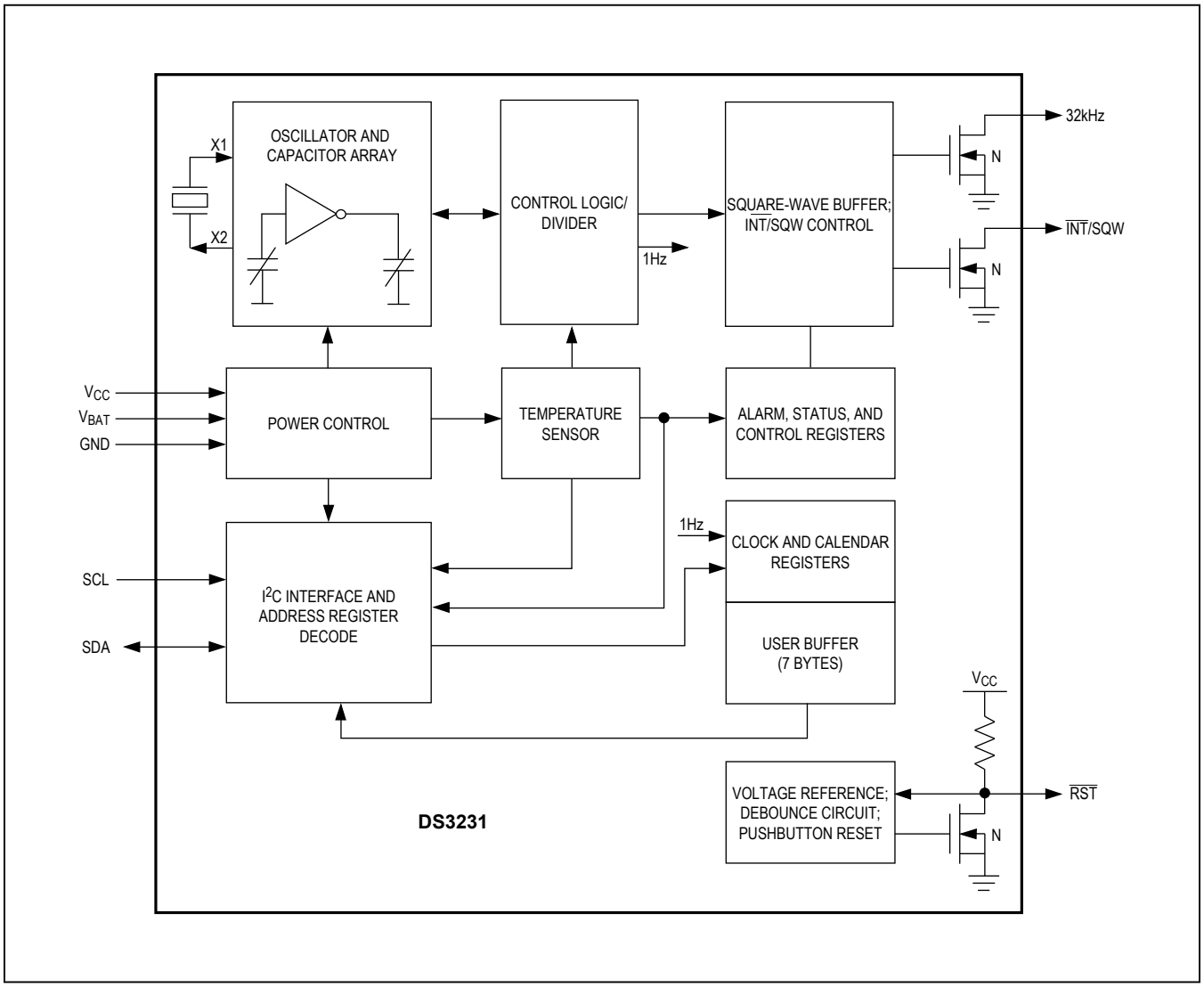
FREQUENCY DEVIATION vs. TEMPERATURE vs. AGING VALUE



DELTA TIME AND FREQUENCY vs. TEMPERATURE



Block Diagram



Pin Description

PIN	NAME	FUNCTION
1	32kHz	32kHz Output. This open-drain pin requires an external pullup resistor. When enabled, the output operates on either power supply. It may be left open if not used.
2	V_{CC}	DC Power Pin for Primary Power Supply. This pin should be decoupled using a 0.1µF to 1.0µF capacitor. If not used, connect to ground.
3	$\overline{INT}$/SQW	Active-Low Interrupt or Square-Wave Output. This open-drain pin requires an external pullup resistor connected to a supply at 5.5V or less. This multifunction pin is determined by the state of the INTCN bit in the Control Register (0Eh). When INTCN is set to logic 0, this pin outputs a square wave and its frequency is determined by RS2 and RS1 bits. When INTCN is set to logic 1, then a match between the timekeeping registers and either of the alarm registers activates the $\overline{INT}$/SQW pin (if the alarm is enabled). Because the INTCN bit is set to logic 1 when power is first applied, the pin defaults to an interrupt output with alarms disabled. The pullup voltage can be up to 5.5V, regardless of the voltage on V_{CC}. If not used, this pin can be left unconnected.
4	$\overline{RST}$	Active-Low Reset. This pin is an open-drain input/output. It indicates the status of V_{CC} relative to the V_{PF} specification. As V_{CC} falls below V_{PF}, the $\overline{RST}$ pin is driven low. When V_{CC} exceeds V_{PF}, for t_{RST}, the $\overline{RST}$ pin is pulled high by the internal pullup resistor. The active-low, open-drain output is combined with a debounced pushbutton input function. This pin can be activated by a pushbutton reset request. It has an internal 50kΩ nominal value pullup resistor to V_{CC}. No external pullup resistors should be connected. If the oscillator is disabled, t_{REC} is bypassed and $\overline{RST}$ immediately goes high.
5–12	N.C.	No Connection. Must be connected to ground.
13	GND	Ground
14	V_{BAT}	Backup Power-Supply Input. When using the device with the V_{BAT} input as the primary power source, this pin should be decoupled using a 0.1µF to 1.0µF low-leakage capacitor. When using the device with the V_{BAT} input as the backup power source, the capacitor is not required. If V_{BAT} is not used, connect to ground. The device is UL recognized to ensure against reverse charging when used with a primary lithium battery. Go to www.maximintegrated.com/qa/info/ul.
15	SDA	Serial Data Input/Output. This pin is the data input/output for the I²C serial interface. This open-drain pin requires an external pullup resistor. The pullup voltage can be up to 5.5V, regardless of the voltage on V_{CC}.
16	SCL	Serial Clock Input. This pin is the clock input for the I²C serial interface and is used to synchronize data movement on the serial interface. Up to 5.5V can be used for this pin, regardless of the voltage on V_{CC}.

Detailed Description

The DS3231 is a serial RTC driven by a temperature-compensated 32kHz crystal oscillator. The TCXO provides a stable and accurate reference clock, and maintains the RTC to within ±2 minutes per year accuracy from -40°C to +85°C. The TCXO frequency output is available at the 32kHz pin. The RTC is a low-power clock/calendar with two programmable time-of-day alarms and a programmable square-wave output. The $\overline{INT}$/SQW provides either an interrupt signal due to alarm conditions or a square-wave output. The clock/calendar provides seconds, minutes, hours, day, date, month, and year information. The date at the end of the month is automatically adjusted for months with fewer than 31 days, including corrections for leap year. The clock operates in either the 24-hour or 12-hour format with an $\overline{AM}$/PM indicator. The internal registers are accessible though an I²C bus interface.

A temperature-compensated voltage reference and comparator circuit monitors the level of V_{CC} to detect power failures and to automatically switch to the backup supply when necessary. The $\overline{RST}$ pin provides an external pushbutton function and acts as an indicator of a power-fail event.

Operation

The block diagram shows the main elements of the DS3231. The eight blocks can be grouped into four functional groups: TCXO, power control, pushbutton function, and RTC. Their operations are described separately in the following sections.

32kHz TCXO

The temperature sensor, oscillator, and control logic form the TCXO. The controller reads the output of the on-chip temperature sensor and uses a lookup table to determine the capacitance required, adds the aging correction in AGE register, and then sets the capacitance selection registers. New values, including changes to the AGE register, are loaded only when a change in the temperature value occurs, or when a user-initiated temperature conversion is completed. Temperature conversion occurs on initial application of V_{CC} and once every 64 seconds afterwards.

Power Control

This function is provided by a temperature-compensated voltage reference and a comparator circuit that monitors the V_{CC} level. When V_{CC} is greater than V_{PF}, the part is powered by V_{CC}. When V_{CC} is less than V_{PF} but greater than V_{BAT}, the DS3231 is powered by V_{CC}. If V_{CC} is less than V_{PF} and is less than V_{BAT}, the device is powered by V_{BAT}. See Table 1.

Table 1. Power Control

SUPPLY CONDITION	ACTIVE SUPPLY
$V_{CC} < V_{PF}$, $V_{CC} < V_{BAT}$	V_{BAT}
$V_{CC} < V_{PF}$, $V_{CC} > V_{BAT}$	V_{CC}
$V_{CC} > V_{PF}$, $V_{CC} < V_{BAT}$	V_{CC}
$V_{CC} > V_{PF}$, $V_{CC} > V_{BAT}$	V_{CC}

To preserve the battery, the first time V_{BAT} is applied to the device, the oscillator will not start up until V_{CC} exceeds V_{PF}, or until a valid I²C address is written to the part. Typical oscillator startup time is less than one second. Approximately 2 seconds after V_{CC} is applied, or a valid I²C address is written, the device makes a temperature measurement and applies the calculated correction to the oscillator. Once the oscillator is running, it continues to run as long as a valid power source is available (V_{CC} or V_{BAT}), and the device continues to measure the temperature and correct the oscillator frequency every 64 seconds.

On the first application of power (V_{CC}) or when a valid I²C address is written to the part (V_{BAT}), the time and date registers are reset to 01/01/00 01 00:00:00 (DD/MM/YY DOW HH:MM:SS).

V_{BAT} Operation

There are several modes of operation that affect the amount of V_{BAT} current that is drawn. While the device is powered by V_{BAT} and the serial interface is active, active battery current, I_{BATA}, is drawn. When the serial interface is inactive, timekeeping current (I_{BATT}), which includes the averaged temperature conversion current, I_{BATTC}, is used (refer to Application Note 3644: *Power Considerations for Accurate Real-Time Clocks* for details). Temperature conversion current, I_{BATTC}, is specified since the system must be able to support the periodic higher current pulse and still maintain a valid voltage level. Data retention current, I_{BATTDR}, is the current drawn by the part when the oscillator is stopped ($\overline{EOSC}$ = 1). This mode can be used to minimize battery requirements for times when maintaining time and date information is not necessary, e.g., while the end system is waiting to be shipped to a customer.

Pushbutton Reset Function

The DS3231 provides for a pushbutton switch to be connected to the $\overline{RST}$ output pin. When the DS3231 is not in a reset cycle, it continuously monitors the $\overline{RST}$ signal for a low going edge. If an edge transition is detected, the DS3231 debounces the switch by pulling the $\overline{RST}$ low. After the internal timer has expired (PB_{DB}), the DS3231 continues to monitor the $\overline{RST}$ line. If the line is still low, the DS3231 continuously monitors the line looking for a rising edge. Upon detecting release, the DS3231 forces the $\overline{RST}$ pin low and holds it low for t_{RST}.

$\overline{RST}$ is also used to indicate a power-fail condition. When V_{CC} is lower than V_{PF}, an internal power-fail signal is generated, which forces the $\overline{RST}$ pin low. When V_{CC} returns to a level above V_{PF}, the $\overline{RST}$ pin is held low for approximately 250ms (t_{REC}) to allow the power supply to stabilize. If the oscillator is not running (see the *Power Control* section) when V_{CC} is applied, t_{REC} is bypassed and $\overline{RST}$ immediately goes high. Assertion of the $\overline{RST}$ output, whether by pushbutton or power-fail detection, does not affect the internal operation of the DS3231.

Real-Time Clock

With the clock source from the TCXO, the RTC provides seconds, minutes, hours, day, date, month, and year information. The date at the end of the month is automatically adjusted for months with fewer than 31 days, including corrections for leap year. The clock operates in either the 24-hour or 12-hour format with an $\overline{AM}$/PM indicator.

The clock provides two programmable time-of-day alarms and a programmable square-wave output. The $\overline{INT}$/SQW pin either generates an interrupt due to alarm condition or outputs a square-wave signal and the selection is controlled by the bit INTCN.

ADDRESS	BIT 7 MSB	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0 LSB	FUNCTION	RANGE
00h	0	10 Seconds			Seconds				Seconds	00–59
01h	0	10 Minutes			Minutes				Minutes	00–59
02h	0	12/$\overline{24}$	$\overline{AM}$/PM 20 Hour	10 Hour	Hour				Hours	1–12 + $\overline{AM}$/PM 00–23
03h	0	0	0	0	0	Day			Day	1–7
04h	0	0	10 Date		Date				Date	01–31
05h	Century	0	0	10 Month	Month				Month/ Century	01–12 + Century
06h	10 Year				Year				Year	00–99
07h	A1M1	10 Seconds			Seconds				Alarm 1 Seconds	00–59
08h	A1M2	10 Minutes			Minutes				Alarm 1 Minutes	00–59
09h	A1M3	12/$\overline{24}$	$\overline{AM}$/PM 20 Hour	10 Hour	Hour				Alarm 1 Hours	1–12 + $\overline{AM}$/PM 00–23
0Ah	A1M4	DY/$\overline{DT}$	10 Date		Day				Alarm 1 Day	1–7
					Date				Alarm 1 Date	1–31
0Bh	A2M2	10 Minutes			Minutes				Alarm 2 Minutes	00–59
0Ch	A2M3	12/$\overline{24}$	$\overline{AM}$/PM 20 Hour	10 Hour	Hour				Alarm 2 Hours	1–12 + $\overline{AM}$/PM 00–23
0Dh	A2M4	DY/$\overline{DT}$	10 Date		Day				Alarm 2 Day	1–7
					Date				Alarm 2 Date	1–31
0Eh	$\overline{EOSC}$	BBSQW	CONV	RS2	RS1	INTCN	A2IE	A1IE	Control	—
0Fh	OSF	0	0	0	EN32kHz	BSY	A2F	A1F	Control/Status	—
10h	SIGN	DATA	DATA	DATA	DATA	DATA	DATA	DATA	Aging Offset	—
11h	SIGN	DATA	DATA	DATA	DATA	DATA	DATA	DATA	MSB of Temp	—
12h	DATA	DATA	0	0	0	0	0	0	LSB of Temp	—

Figure 1. Timekeeping Registers

Note: *Unless otherwise specified, the registers' state is not defined when power is first applied.*

Address Map

Figure 1 shows the address map for the DS3231 timekeeping registers. During a multibyte access, when the address pointer reaches the end of the register space (12h), it wraps around to location 00h. On an I²C START or address pointer incrementing to location 00h, the current time is transferred to a second set of registers. The time information is read from these secondary registers, while the clock may continue to run. This eliminates the need to reread the registers in case the main registers update during a read.

I²C Interface

The I²C interface is accessible whenever either V_{CC} or V_{BAT} is at a valid level. If a microcontroller connected to the DS3231 resets because of a loss of V_{CC} or other event, it is possible that the microcontroller and DS3231 I²C communications could become unsynchronized, e.g., the microcontroller resets while reading data from the DS3231. When the microcontroller resets, the DS3231 I²C interface may be placed into a known state by toggling SCL until SDA is observed to be at a high level. At that point the microcontroller should pull SDA low while SCL is high, generating a START condition.

Clock and Calendar

The time and calendar information is obtained by reading the appropriate register bytes. Figure 1 illustrates the RTC registers. The time and calendar data are set or initialized by writing the appropriate register bytes. The contents of the time and calendar registers are in the binary-coded

decimal (BCD) format. The DS3231 can be run in either 12-hour or 24-hour mode. Bit 6 of the hours register is defined as the 12- or 24-hour mode select bit. When high, the 12-hour mode is selected. In the 12-hour mode, bit 5 is the AM/PM bit with logic-high being PM. In the 24-hour mode, bit 5 is the 20-hour bit (20–23 hours). The century bit (bit 7 of the month register) is toggled when the years register overflows from 99 to 00.

The day-of-week register increments at midnight. Values that correspond to the day of week are user-defined but must be sequential (i.e., if 1 equals Sunday, then 2 equals Monday, and so on). Illogical time and date entries result in undefined operation.

When reading or writing the time and date registers, secondary (user) buffers are used to prevent errors when the internal registers update. When reading the time and date registers, the user buffers are synchronized to the internal registers on any START and when the register pointer rolls over to zero. The time information is read from these secondary registers, while the clock continues to run. This eliminates the need to reread the registers in case the main registers update during a read.

The countdown chain is reset whenever the seconds register is written. Write transfers occur on the acknowledge from the DS3231. Once the countdown chain is reset, to avoid rollover issues the remaining time and date registers must be written within 1 second. The 1Hz square-wave output, if enabled, transitions high 500ms after the seconds data transfer, provided the oscillator is already running.

Alarms

The DS3231 contains two time-of-day/date alarms. Alarm 1 can be set by writing to registers 07h to 0Ah. Alarm 2 can be set by writing to registers 0Bh to 0Dh. The alarms can be programmed (by the alarm enable and INTCN bits of the control register) to activate the INT/SQW output on an alarm match condition. Bit 7 of each of the time-of-day/date alarm registers are mask bits (Table 2). When all the mask bits for each alarm are logic 0, an alarm only occurs when the values in the timekeeping registers match the corresponding values stored in the time-of-day/date alarm registers. The alarms can also be programmed to repeat every second, minute, hour, day, or date. Table 2 shows the possible settings. Configurations not listed in the table will result in illogical operation.

The DY/DT bits (bit 6 of the alarm day/date registers) control whether the alarm value stored in bits 0 to 5 of that register reflects the day of the week or the date of the month. If DY/DT is written to logic 0, the alarm will be the result of a match with date of the month. If DY/DT is written to logic 1, the alarm will be the result of a match with day of the week.

When the RTC register values match alarm register settings, the corresponding Alarm Flag ‘A1F’ or ‘A2F’ bit is set to logic 1. If the corresponding Alarm Interrupt Enable ‘A1IE’ or ‘A2IE’ is also set to logic 1 and the INTCN bit is set to logic 1, the alarm condition will activate the INT/SQW signal. The match is tested on the once-per-second update of the time and date registers.

Table 2. Alarm Mask Bits

DY/DT	ALARM 1 REGISTER MASK BITS (BIT 7)				ALARM RATE
	A1M4	A1M3	A1M2	A1M1	
X	1	1	1	1	Alarm once per second
X	1	1	1	0	Alarm when seconds match
X	1	1	0	0	Alarm when minutes and seconds match
X	1	0	0	0	Alarm when hours, minutes, and seconds match
0	0	0	0	0	Alarm when date, hours, minutes, and seconds match
1	0	0	0	0	Alarm when day, hours, minutes, and seconds match

DY/DT	ALARM 2 REGISTER MASK BITS (BIT 7)			ALARM RATE
	A2M4	A2M3	A2M2	
X	1	1	1	Alarm once per minute (00 seconds of every minute)
X	1	1	0	Alarm when minutes match
X	1	0	0	Alarm when hours and minutes match
0	0	0	0	Alarm when date, hours, and minutes match
1	0	0	0	Alarm when day, hours, and minutes match

Control Register (0Eh)

	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
NAME:	$\overline{EOSC}$	BBSQW	CONV	RS2	RS1	INTCN	A2IE	A1IE
POR:	0	0	0	1	1	1	0	0

Special-Purpose Registers

The DS3231 has two additional registers (control and status) that control the real-time clock, alarms, and square-wave output.

Control Register (0Eh)

Bit 7: Enable Oscillator ($\overline{EOSC}$). When set to logic 0, the oscillator is started. When set to logic 1, the oscillator is stopped when the DS3231 switches to V_{BAT}. This bit is clear (logic 0) when power is first applied. When the DS3231 is powered by V_{CC}, the oscillator is always on regardless of the status of the $\overline{EOSC}$ bit. When $\overline{EOSC}$ is disabled, all register data is static.

Bit 6: Battery-Backed Square-Wave Enable (BBSQW). When set to logic 1 with INTCN = 0 and $V_{CC} < V_{PF}$, this bit enables the square wave. When BBSQW is logic 0, the $\overline{INT}$/SQW pin goes high impedance when $V_{CC} < V_{PF}$. This bit is disabled (logic 0) when power is first applied.

Bit 5: Convert Temperature (CONV). Setting this bit to 1 forces the temperature sensor to convert the temperature into digital code and execute the TCXO algorithm to update the capacitance array to the oscillator. This can only happen when a conversion is not already in progress. The user should check the status bit BSY before forcing the controller to start a new TCXO execution. A user-initiated temperature conversion does not affect the internal 64-second update cycle.

A user-initiated temperature conversion does not affect the BSY bit for approximately 2ms. The CONV bit remains at a 1 from the time it is written until the conversion is finished, at which time both CONV and BSY go to 0. The CONV bit should be used when monitoring the status of a user-initiated conversion.

Bits 4 and 3: Rate Select (RS2 and RS1). These bits control the frequency of the square-wave output when the square wave has been enabled. The following table shows the square-wave frequencies that can be selected with the RS bits. These bits are both set to logic 1 (8.192kHz) when power is first applied.

SQUARE-WAVE OUTPUT FREQUENCY

RS2	RS1	SQUARE-WAVE OUTPUT FREQUENCY
0	0	1Hz
0	1	1.024kHz
1	0	4.096kHz
1	1	8.192kHz

Bit 2: Interrupt Control (INTCN). This bit controls the $\overline{INT}$/SQW signal. When the INTCN bit is set to logic 0, a square wave is output on the $\overline{INT}$/SQW pin. When the INTCN bit is set to logic 1, then a match between the timekeeping registers and either of the alarm registers activates the $\overline{INT}$/SQW output (if the alarm is also enabled). The corresponding alarm flag is always set regardless of the state of the INTCN bit. The INTCN bit is set to logic 1 when power is first applied.

Bit 1: Alarm 2 Interrupt Enable (A2IE). When set to logic 1, this bit permits the alarm 2 flag (A2F) bit in the status register to assert $\overline{INT}$/SQW (when INTCN = 1). When the A2IE bit is set to logic 0 or INTCN is set to logic 0, the A2F bit does not initiate an interrupt signal. The A2IE bit is disabled (logic 0) when power is first applied.

Bit 0: Alarm 1 Interrupt Enable (A1IE). When set to logic 1, this bit permits the alarm 1 flag (A1F) bit in the status register to assert $\overline{INT}$/SQW (when INTCN = 1). When the A1IE bit is set to logic 0 or INTCN is set to logic 0, the A1F bit does not initiate the $\overline{INT}$/SQW signal. The A1IE bit is disabled (logic 0) when power is first applied.

Status Register (0Fh)

	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
NAME:	OSF	0	0	0	EN32kHz	BSY	A2F	A1F
POR:	1	0	0	0	1	X	X	X

Status Register (0Fh)

Bit 7: Oscillator Stop Flag (OSF). A logic 1 in this bit indicates that the oscillator either is stopped or was stopped for some period and may be used to judge the validity of the timekeeping data. This bit is set to logic 1 any time that the oscillator stops. The following are examples of conditions that can cause the OSF bit to be set:

1) The first time power is applied.
2) The voltages present on both V_{CC} and V_{BAT} are insufficient to support oscillation.
3) The $\overline{EOSC}$ bit is turned off in battery-backed mode.
4) External influences on the crystal (i.e., noise, leakage, etc.).

This bit remains at logic 1 until written to logic 0.

Bit 3: Enable 32kHz Output (EN32kHz). This bit controls the status of the 32kHz pin. When set to logic 1, the 32kHz pin is enabled and outputs a 32.768kHz square-wave signal. When set to logic 0, the 32kHz pin goes to a high-impedance state. The initial power-up state of this bit is logic 1, and a 32.768kHz square-wave signal appears at the 32kHz pin after a power source is applied to the DS3231 (if the oscillator is running).

Bit 2: Busy (BSY). This bit indicates the device is busy executing TCXO functions. It goes to logic 1 when the conversion signal to the temperature sensor is asserted and then is cleared when the device is in the 1-minute idle state.

Bit 1: Alarm 2 Flag (A2F). A logic 1 in the alarm 2 flag bit indicates that the time matched the alarm 2 registers. If the A2IE bit is logic 1 and the INTCN bit is set to logic 1, the $\overline{INT}$/SQW pin is also asserted. A2F is cleared when written to logic 0. This bit can only be written to logic 0. Attempting to write to logic 1 leaves the value unchanged.

Bit 0: Alarm 1 Flag (A1F). A logic 1 in the alarm 1 flag bit indicates that the time matched the alarm 1 registers. If the A1IE bit is logic 1 and the INTCN bit is set to logic 1, the $\overline{INT}$/SQW pin is also asserted. A1F is cleared when written to logic 0. This bit can only be written to logic 0. Attempting to write to logic 1 leaves the value unchanged.

Aging Offset

The aging offset register takes a user-provided value to add to or subtract from the codes in the capacitance array registers. The code is encoded in two's complement, with bit 7 representing the sign bit. One LSB represents one small capacitor to be switched in or out of the capacitance array at the crystal pins. The aging offset register capacitance value is added or subtracted from the capacitance value that the device calculates for each temperature compensation. The offset register is added to the capacitance array during a normal temperature conversion, if the temperature changes from the previous conversion, or during a manual user conversion (setting the CONV bit). To see the effects of the aging register on the 32kHz output frequency immediately, a manual conversion should be started after each aging register change.

Positive aging values add capacitance to the array, slowing the oscillator frequency. Negative values remove capacitance from the array, increasing the oscillator frequency.

The change in ppm per LSB is different at different temperatures. The frequency vs. temperature curve is shifted by the values used in this register. At +25°C, one LSB typically provides about 0.1ppm change in frequency.

Use of the aging register is not needed to achieve the accuracy as defined in the EC tables, but could be used to help compensate for aging at a given temperature. See the *Typical Operating Characteristics* section for a graph showing the effect of the register on accuracy over temperature.

Aging Offset (10h)

	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
NAME:	Sign	Data	Data	Data	Data	Data	Data	Data
POR:	0	0	0	0	0	0	0	0

Temperature Register (Upper Byte) (11h)

	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
NAME:	Sign	Data	Data	Data	Data	Data	Data	Data
POR:	0	0	0	0	0	0	0	0

Temperature Register (Lower Byte) (12h)

	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
NAME:	Data	Data	0	0	0	0	0	0
POR:	0	0	0	0	0	0	0	0

Temperature Registers (11h–12h)

Temperature is represented as a 10-bit code with a resolution of 0.25°C and is accessible at location 11h and 12h. The temperature is encoded in two's complement format. The upper 8 bits, the integer portion, are at location 11h and the lower 2 bits, the fractional portion, are in the upper nibble at location 12h. For example, 00011001 01b = +25.25°C. Upon power reset, the registers are set to a default temperature of 0°C and the controller starts a temperature conversion. The temperature is read on initial application of V_{CC} or I2C access on V_{BAT} and once every 64 seconds afterwards. The temperature registers are updated after each user-initiated conversion and on every 64-second conversion. The temperature registers are read-only.

I2C Serial Data Bus

The DS3231 supports a bidirectional I2C bus and data transmission protocol. A device that sends data onto the bus is defined as a transmitter and a device receiving data is defined as a receiver. The device that controls the message is called a master. The devices that are controlled by the master are slaves. The bus must be controlled by a master device that generates the serial clock (SCL), controls the bus access, and generates the START and STOP conditions. The DS3231 operates as a slave on the I2C bus. Connections to the bus are made through the SCL input and open-drain SDA I/O lines. Within the bus specifications, a standard mode (100kHz maximum clock rate) and a fast mode (400kHz maximum clock rate) are defined. The DS3231 works in both modes.

The following bus protocol has been defined (Figure 2):

- Data transfer may be initiated only when the bus is not busy.
- During data transfer, the data line must remain stable whenever the clock line is high. Changes in the data line while the clock line is high are interpreted as control signals.

Accordingly, the following bus conditions have been defined:

Bus not busy: Both data and clock lines remain high.

START data transfer: A change in the state of the data line from high to low, while the clock line is high, defines a START condition.

STOP data transfer: A change in the state of the data line from low to high, while the clock line is high, defines a STOP condition.

Data valid: The state of the data line represents valid data when, after a START condition, the data line is stable for the duration of the high period of the clock signal. The data on the line must be changed during the low period of the clock signal. There is one clock pulse per bit of data.

Each data transfer is initiated with a START condition and terminated with a STOP condition. The number of data bytes transferred between the START and the STOP conditions is not limited, and is determined by the master device. The information is transferred byte-wise and each receiver acknowledges with a ninth bit.

Acknowledge: Each receiving device, when addressed, is obliged to generate an acknowledge after the reception of each byte. The master device must generate an extra clock pulse, which is associated with this acknowledge bit.

A device that acknowledges must pull down the SDA line during the acknowledge clock pulse in such a way that the SDA line is stable low during the high period of the acknowledge-related clock pulse. Of course, setup and hold times must be taken into account. A master must signal an end of data to the slave by not generat-

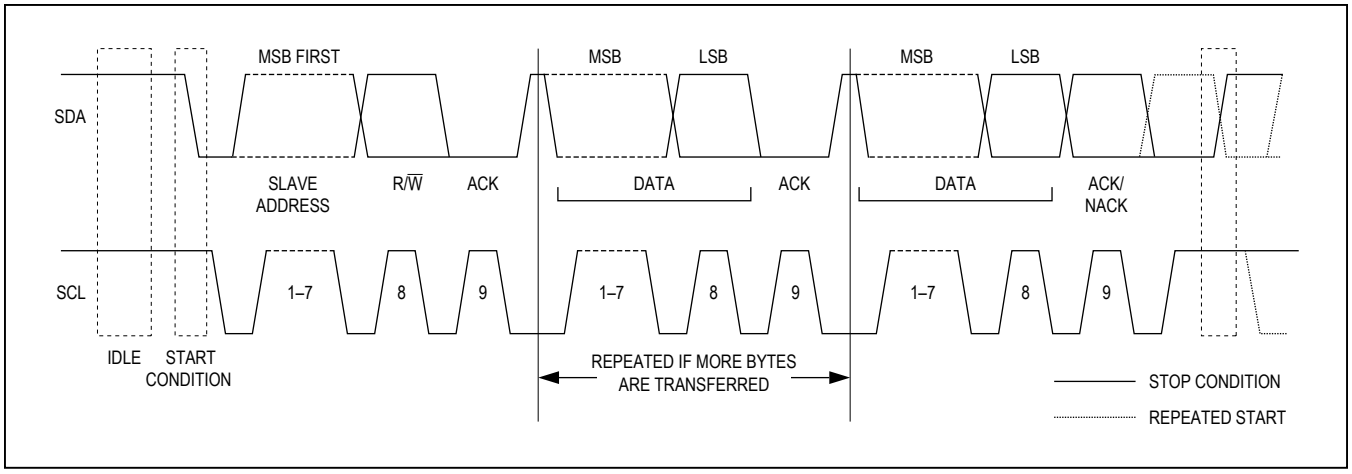


Figure 2. I2C Data Transfer Overview

ing an acknowledge bit on the last byte that has been clocked out of the slave. In this case, the slave must leave the data line high to enable the master to generate the STOP condition.

Figures 3 and 4 detail how data transfer is accomplished on the I2C bus. Depending upon the state of the R/$\overline{W}$ bit, two types of data transfer are possible:

Data transfer from a master transmitter to a slave receiver. The first byte transmitted by the master is the slave address. Next follows a number of data bytes. The slave returns an acknowledge bit after each received byte. Data is transferred with the most significant bit (MSB) first.

Data transfer from a slave transmitter to a master receiver. The first byte (the slave address) is transmitted by the master. The slave then returns an acknowledge bit. Next follows a number of data bytes transmitted by the slave to the master. The master returns an acknowledge bit after all received bytes other than the

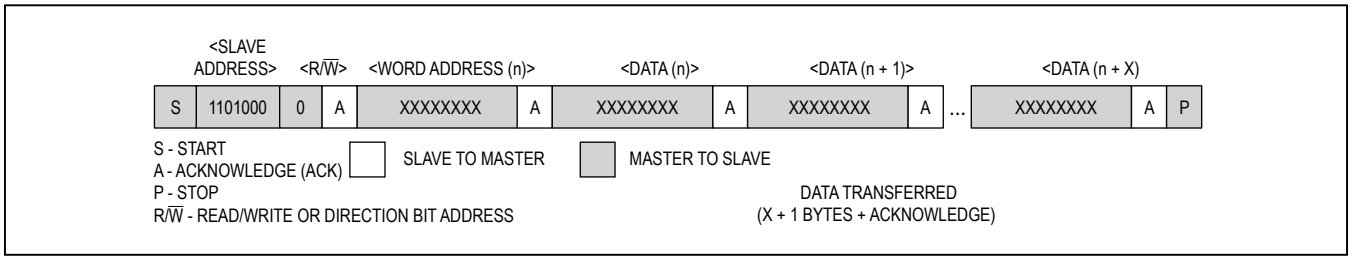


Figure 3. Data Write—Slave Receiver Mode

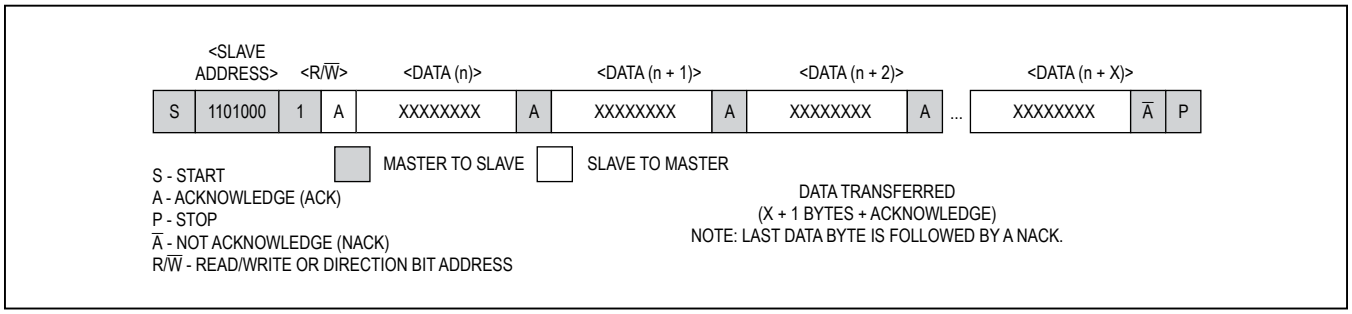


Figure 4. Data Read—Slave Transmitter Mode

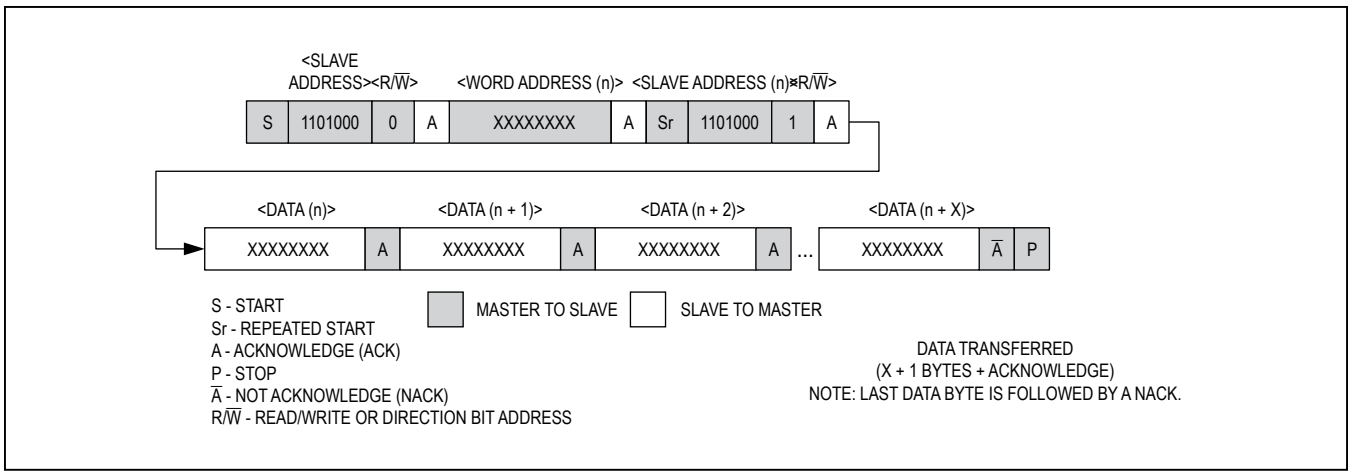


Figure 5. Data Write/Read (Write Pointer, Then Read)—Slave Receive and Transmit

last byte. At the end of the last received byte, a not acknowledge is returned.

The master device generates all the serial clock pulses and the START and STOP conditions. A transfer is ended with a STOP condition or with a repeated START condition. Since a repeated START condition is also the beginning of the next serial transfer, the bus will not be released. Data is transferred with the most significant bit (MSB) first.

The DS3231 can operate in the following two modes:

Slave receiver mode (DS3231 write mode): Serial data and clock are received through SDA and SCL. After each byte is received, an acknowledge bit is transmitted. START and STOP conditions are recognized as the beginning and end of a serial transfer. Address recognition is performed by hardware after reception of the slave address and direction bit. The slave address byte is the first byte received after the master generates the START condition. The slave address byte contains the 7-bit DS3231 address, which is 1101000, followed by the direction bit (R/$\overline{W}$), which is 0 for a write. After receiving and decoding the slave address byte, the DS3231 outputs an acknowledge on SDA. After the DS3231 acknowledges the slave address + write bit, the master transmits a word address to the DS3231. This sets the register pointer on the DS3231, with the DS3231 acknowledging the transfer. The master may then transmit zero or more bytes of data, with the DS3231 acknowledging each byte received. The register pointer increments after each data byte is transferred. The master generates a STOP condition to terminate the data write.

Slave transmitter mode (DS3231 read mode): The first byte is received and handled as in the slave receiver mode. However, in this mode, the direction bit indicates that the transfer direction is reversed. Serial data is transmitted on SDA by the DS3231 while the serial clock is input on SCL. START and STOP conditions are recognized as the beginning and end of a serial transfer. Address recognition is performed by hardware after reception of the slave address and direction bit. The slave address byte is the first byte received after the master generates a START condition. The slave address byte contains the 7-bit DS3231 address, which is 1101000, followed by the direction bit (R/$\overline{W}$), which is 1 for a read. After receiving and decoding the slave address byte, the DS3231 outputs an acknowledge on SDA. The DS3231 then begins to transmit data starting with the register address pointed to by the register pointer. If the register pointer is not written to before the initiation of a read mode, the first address that is read is the last one stored in the register pointer. The DS3231 must receive a not acknowledge to end a read.

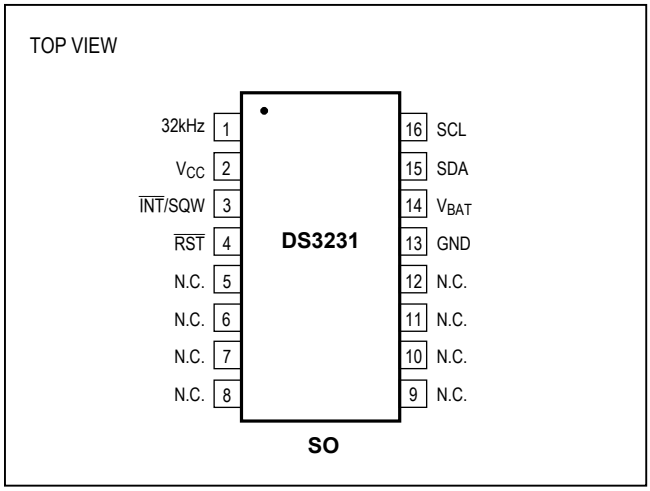
Handling, PCB Layout, and Assembly

The DS3231 package contains a quartz tuning-fork crystal. Pick-and-place equipment can be used, but precautions should be taken to ensure that excessive shocks are avoided. Ultrasonic cleaning should be avoided to prevent damage to the crystal.

Avoid running signal traces under the package, unless a ground plane is placed between the package and the signal line. All N.C. (no connect) pins must be connected to ground.

Moisture-sensitive packages are shipped from the factory dry packed. Handling instructions listed on the package label must be followed to prevent damage during reflow. Refer to the IPC/JEDEC J-STD-020 standard for moisture-sensitive device (MSD) classifications and reflow profiles. Exposure to reflow is limited to 2 times maximum.

Pin Configuration



Chip Information

SUBSTRATE CONNECTED TO GROUND

PROCESS: CMOS

Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
DS3231S#	0°C to +70°C	16 SO
DS3231SN#	-40°C to +85°C	16 SO

#Denotes an RoHS-compliant device that may include lead (Pb) that is exempt under RoHS requirements. The lead finish is JESD97 category e3, and is compatible with both lead-based and lead-free soldering processes. A "#" anywhere on the top mark denotes an RoHS-compliant device.

Package Information

For the latest package outline information and land patterns (footprints), go to **www.maximintegrated.com/packages**. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
16 SO	W16#H2	21-0042	90-0107

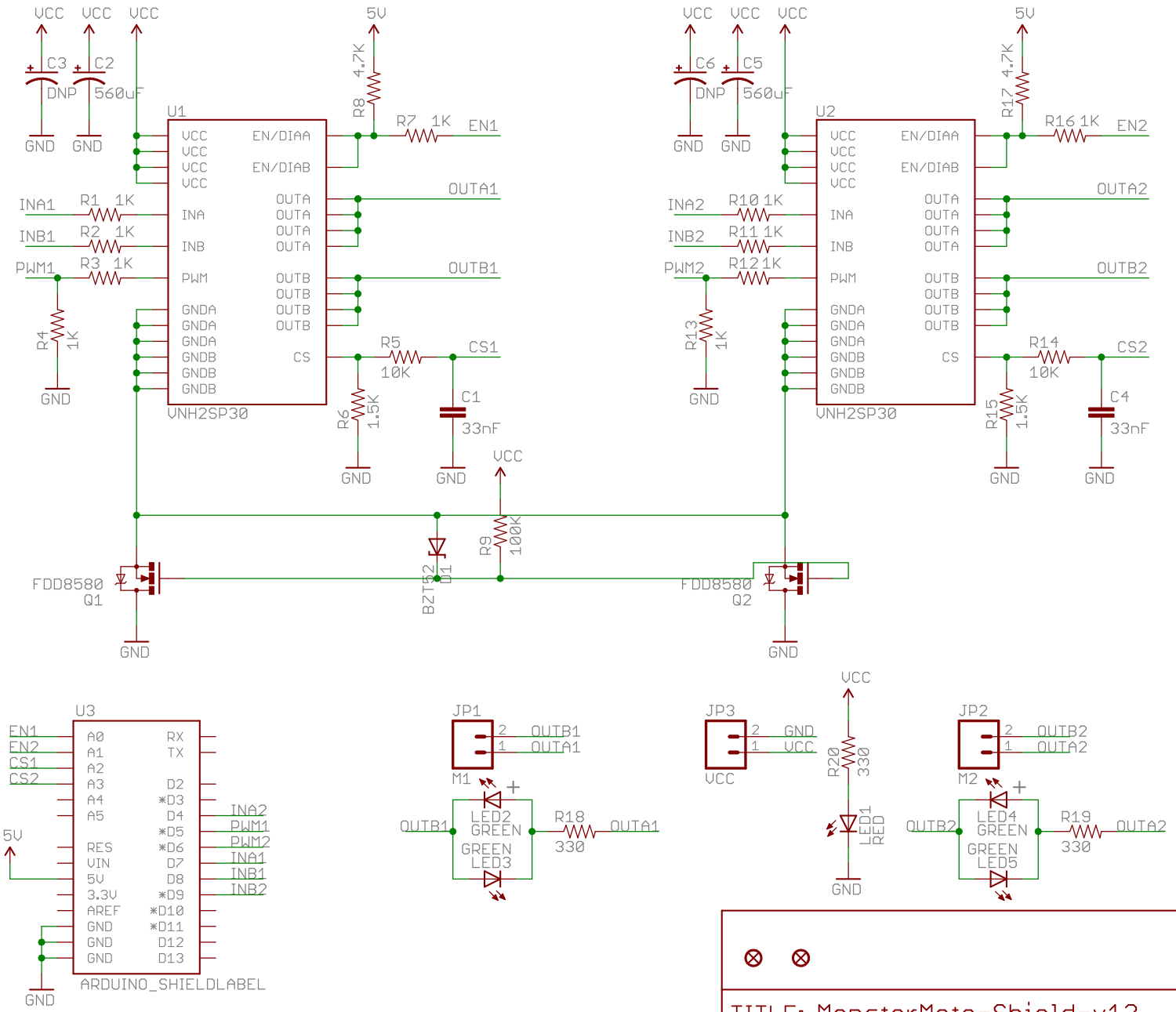
Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	1/05	Initial release.	—
1	2/05	Changed Digital Temp Sensor Output from ±2°C to ±3°C.	1, 3
		Updated *Typical Operating Circuit*.	1
		Changed T_A = -40°C to +85°C to T_A = T_{MIN} to T_{MAX}.	2, 3, 4
		Updated *Block Diagram*.	8
2	6/05	Added “UL Recognized” to Features; added lead-free packages and removed S from top mark info in *Ordering Information* table; added ground connections to the N.C. pin in the Typical Operating Circuit.	1
		Added “noncondensing” to operating temperature range; changed V_{PF} MIN from 2.35V to 2.45V.	2
		Added aging offset specification.	3
		Relabeled TOC4.	7
		Added arrow showing input on X1 in the *Block Diagram*.	8
		Updated pin descriptions for V_{CC} and V_{BAT}.	9
		Added the I²C Interface section.	10
		Figure 1: Added sign bit to aging and temperature registers; added MSB and LSB.	11
		Corrected title for rate select bits frequency table.	13
		Added note that frequency stability over temperature spec is with aging offset register = 00h; changed bit 7 from Data to Sign (Crystal Aging Offset Register).	14
		Changed bit 7 from Data to Sign (Temperature Register); correct pin definitions in *I²C Serial Data Bus* section.	15
		Modified the *Handing*, *PC Board Layout*, and *Assembly* section to refer to J-STD-020 for reflow profiles for lead-free and leaded packages.	17
3	11/05	Changed lead-free packages to RoHS-compliant packages.	1
4	10/06	Changed $\overline{RST}$ and UL bullets in *Features*.	1
		Changed EC condition “V_{CC} > V_{BAT}” to “V_{CC} = Active Supply (see Table 1).”	2, 3
		Modified Note 12 to correct t_{REC} operation.	6
		Added various conditions text to TOCs 1, 2, and 3.	7
		Added text to pin descriptions for 32kHz, V_{CC}, and $\overline{RST}$.	9
		Table 1: Changed column heading “Powered By” to “Active Supply”; changed “applied” to “exceeds V_{PF}” in the *Power Control* section.	10
		Indicated BBSQW applies to both SQW and interrupts; simplified temp convert description (bit 5); added “output” to $\overline{INT}$/SQW (bit 2).	13
		Changed the *Crystal Aging* section to the *Aging Offset* section; changed “this bit indicates” to “this bit controls” for the enable 32kHz output bit.	14
5	4/08	Added Warning note to EC table notes; updated Note 12.	6
		Updated the *Typical Operating Characteristics* graphs.	7
		In the *Power Control* section, added information about the POR state of the time and date registers; in the *Real-Time Clock* section, added to the description of the RST function.	10
		In Figure 1, corrected the months date range for 04h from 00–31 to 01–31.	11

Revision History (continued)

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
6	10/08	Updated the *Typical Operating Circuit*.	1
		Removed the V_{PU} parameter from the *Recommended DC Operating Conditions* table and added verbiage about the pullup to the *Pin Description* table for $\overline{INT}$/SQW, SDA, and SCL.	2, 9
		Added the Delta Time and Frequency vs. Temperature graph in the *Typical Operating Characteristics* section.	7
		Updated the *Block Diagram*.	8
		Added the *V_{BAT} Operation* section, improved some sections of text for the *32kHz TCXO* and *Pushbutton Reset Function* sections.	10
		Added the register bit POR values to the register tables.	13, 14, 15
		Updated the *Aging Offset* and *Temperature Registers (11h–12h)* sections.	14, 15
		Updated the I2C timing diagrams (Figures 3, 4, and 5).	16, 17
7	3/10	Removed the “S” from the top mark in the *Ordering Information* table and the *Pin Configuration* to match the packaging engineering marking specification.	1, 18
8	7/10	Updated the *Typical Operating Circuit*; removed the “Top Mark” column from the *Ordering Information*; in the *Absolute Maximum Ratings* section, added the theta-JA and theta-JC thermal resistances and Note 1, and changed the soldering temperature to +260°C (lead(Pb)-free) and +240°C (leaded); updated the functional description of the V_{BAT} pin in the *Pin Description*; changed the timekeeping registers 02h, 09h, and 0Ch to “20 Hour” in Bit 5 of Figure 1; updated the BBSQW bit description in the *Control Register (0Eh)* section; added the land pattern no. to the *Package Information* table.	1, 2, 3, 4, 6, 9, 11, 12, 13, 18
9	1/13	Updated *Absolute Maximum Ratings*, and last paragraph in *Power Control* section	2, 10
10	3/15	Revised *Benefits and Features* section.	1

LAMPIRAN 4



Design by: Nate Bernstein
Jim Lindblom

TITLE: MonsterMoto-Shield-v12	SFE
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LAMPIRAN 5

VNH2SP30-E

Automotive fully integrated H-bridge motor driver

Features

Type	$R_{DS(on)}$	I_{out}	V_{ccmax}
VNH2SP30-E	19mΩ max (per leg)	30A	41V

- 5V logic level compatible inputs
- Undervoltage and overvoltage shut-down
- Overvoltage clamp
- Thermal shut down
- Cross-conduction protection
- Linear current limiter
- Very low stand-by power consumption
- PWM operation up to 20 kHz
- Protection against loss of ground and loss of V_{CC}
- Current sense output proportional to motor current
- Package: ECOPACK®

MultiPowerSO-30™

Description

The VNH2SP30-E is a full bridge motor driver intended for a wide range of automotive applications. The device incorporates a dual monolithic high side driver and two low side switches. The high side driver switch is designed using STMicroelectronic's well known and proven proprietary VIPower™ M0 technology which permits efficient integration on the same die of a true Power MOSFET with an intelligent signal/protection circuitry.

The low side switches are vertical MOSFETs manufactured using STMicroelectronic's proprietary EHD ('STripFET™') process. The three die are assembled in the MultiPowerSO-30 package on electrically isolated leadframes. This package, specifically designed for the harsh automotive environment offers improved thermal performance thanks to exposed die pads. Moreover, its fully symmetrical mechanical design allows superior manufacturability at board level. The input signals IN_A and IN_B can directly interface to the microcontroller to select the motor direction and the brake condition. The $DIAG_A/EN_A$ or $DIAG_B/EN_B$, when connected to an external pull-up resistor, enable one leg of the bridge. They also provide a feedback digital diagnostic signal. The normal condition operation is explained in *Table 12: Truth table in normal operating conditions on page 14*. The motor current can be monitored with the CS pin by delivering a current proportional to its value. The speed of the motor can be controlled in all possible conditions by the PWM up to 20 kHz. In all cases, a low level state on the PWM pin will turn off both the LS_A and LS_B switches. When PWM rises to a high level, LS_A or LS_B turn on again depending on the input pin state.

Table 1. Device summary

Package	Order codes	
	Tube	Tape and Reel
MultiPowerSO-30	VNH2SP30-E	VNH2SP30TR-E

Contents

List of tables

List of figures

1 Block diagram and pin description

Figure 1. Block diagram

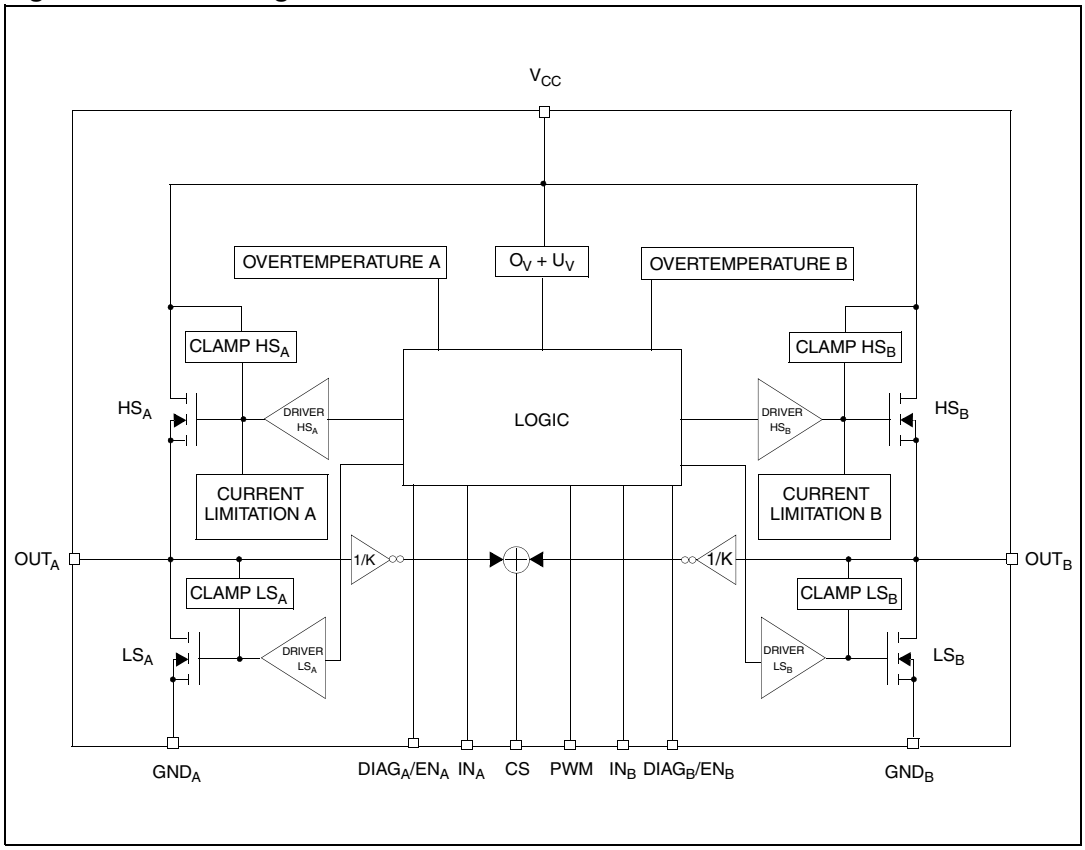


Table 2. Block description

Name	Description
Logic control	Allows the turn-on and the turn-off of the high side and the low side switches according to the truth table
Overvoltage + undervoltage	Shuts down the device outside the range [5.5V..16V] for the battery voltage
High side and low side clamp voltage	Protects the high side and the low side switches from the high voltage on the battery line in all configurations for the motor
High side and low side driver	Drives the gate of the concerned switch to allow a proper $R_{DS(on)}$ for the leg of the bridge
Linear current limiter	Limits the motor current by reducing the high side switch gate-source voltage when short-circuit to ground occurs
Overtemperature protection	In case of short-circuit with the increase of the junction's temperature, shuts down the concerned high side to prevent its degradation and to protect the die
Fault detection	Signals an abnormal behavior of the switches in the half-bridge A or B by pulling low the concerned $EN_x/DIAG_x$ pin

Figure 2. Configuration diagram (top view)

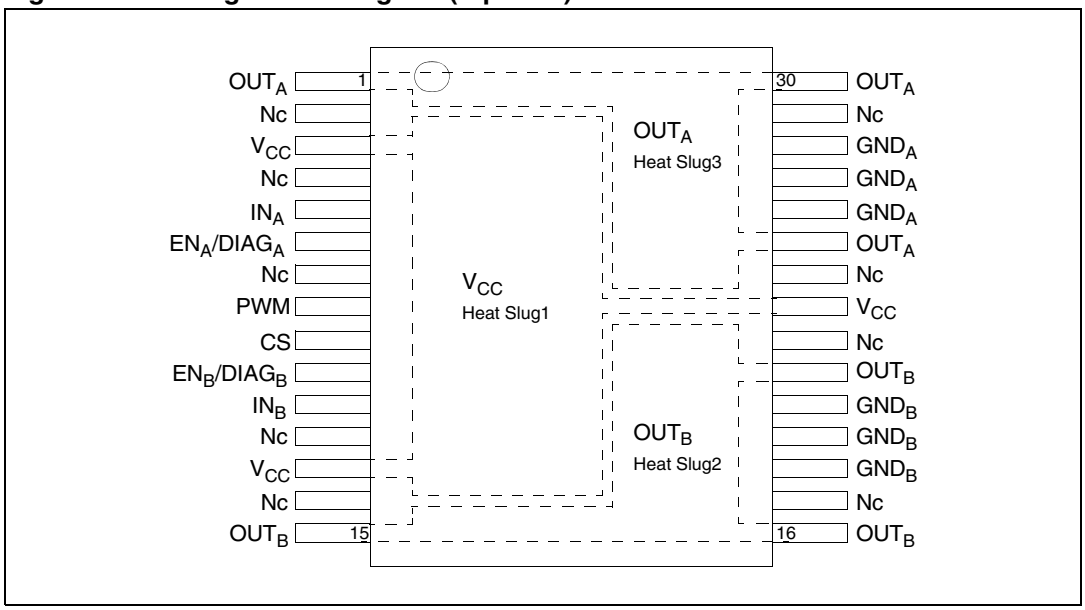


Table 3. Pin definitions and functions

Pin No	Symbol	Function
1, 25, 30	OUT_A, Heat Slug3	Source of high side switch A / Drain of low side switch A
2, 4, 7, 12, 14, 17, 22, 24, 29	NC	Not connected
3, 13, 23	V_{CC}, Heat Slug1	Drain of high side switches and power supply voltage
6	$EN_A/DIAG_A$	Status of high side and low side switches A; open drain output
5	IN_A	Clockwise input
8	PWM	PWM input
9	CS	Output of current sense
11	IN_B	Counter clockwise input
10	$EN_B/DIAG_B$	Status of high side and low side switches B; open drain output
15, 16, 21	OUT_B, Heat Slug2	Source of high side switch B / Drain of low side switch B
26, 27, 28	GND_A	Source of low side switch A(1)
18, 19, 20	GND_B	Source of low side switch B(1)

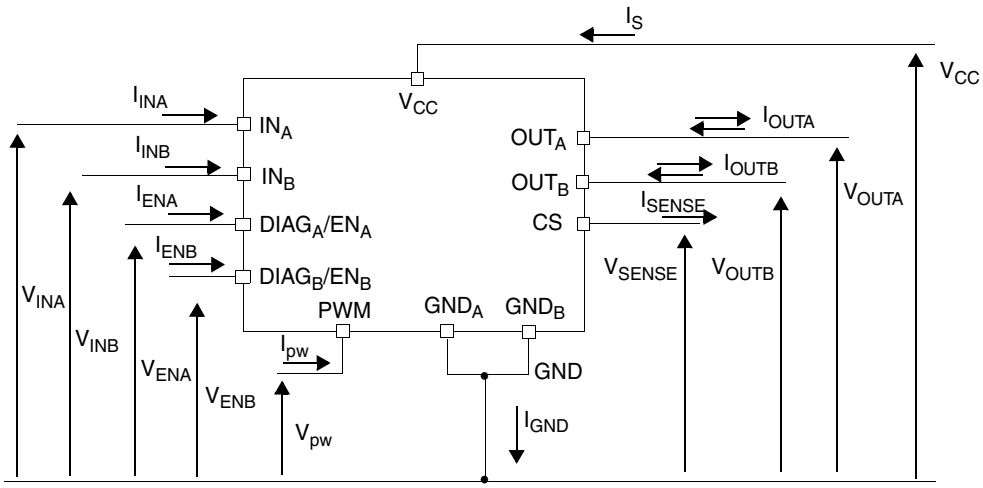
1. GND_A and GND_B must be externally connected together.

Table 4. Pin functions description

Name	Description
V_{CC}	Battery connection
GND_A, GND_B	Power grounds; must always be externally connected together
OUT_A, OUT_B	Power connections to the motor
IN_A, IN_B	Voltage controlled input pins with hysteresis, CMOS compatible. These two pins control the state of the bridge in normal operation according to the truth table (brake to V_{CC}, brake to GND, clockwise and counterclockwise).
PWM	Voltage controlled input pin with hysteresis, CMOS compatible. Gates of low side FETs are modulated by the PWM signal during their ON phase allowing speed control of the motor.
$EN_A/DIAG_A$, $EN_B/DIAG_B$	Open drain bidirectional logic pins. These pins must be connected to an external pull up resistor. When externally pulled low, they disable half-bridge A or B. In case of fault detection (thermal shutdown of a high side FET or excessive ON state voltage drop across a low side FET), these pins are pulled low by the device (see truth table in fault condition).
CS	Analog current sense output. This output sources a current proportional to the motor current. The information can be read back as an analog voltage across an external resistor.

2 Electrical specifications

Figure 3. Current and voltage conventions



2.1 Absolute maximum ratings

Table 5. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CC}	Supply voltage	+41	V
I_{max}	Maximum output current (continuous)	30	A
I_R	Reverse output current (continuous)	-30	
I_{IN}	Input current (IN_A and IN_B pins)	±10	mA
I_{EN}	Enable input current ($DIAG_A/EN_A$ and $DIAG_B/EN_B$ pins)	±10	
I_{pw}	PWM input current	±10	
V_{CS}	Current sense maximum voltage	-3/+15	V
V_{ESD}	Electrostatic discharge (R = 1.5kΩ, C = 100pF) – CS pin – logic pins – output pins: OUT_A, OUT_B, V_{CC}	 2 4 5	 kV kV kV
T_j	Junction operating temperature	Internally limited	°C
T_c	Case operating temperature	-40 to 150	
T_{STG}	Storage temperature	-55 to 150	

2.2 Electrical characteristics

V_{CC} = 9V up to 16 V; -40°C < T_J < 150°C, unless otherwise specified.

Table 6. Power section

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
V_{CC}	Operating supply voltage		5.5		16	V
I_S	Supply current	Off state with all Fault Cleared & ENx=0 IN_A = IN_B = PWM = 0; T_j = 25°C; V_{CC} = 13V IN_A = IN_B = PWM = 0 Off state: IN_A = IN_B = PWM = 0		12 2	30 60	µA µA mA
		On state: IN_A or IN_B = 5V, no PWM			10	mA
R_{ONHS}	Static high side resistance	I_{OUT} = 15A; T_j = 25°C			14	mΩ
		I_{OUT} = 15A; T_j = -40 to 150°C			28	
R_{ONLS}	Static low side resistance	I_{OUT} = 15A; T_j = 25°C			5	
		I_{OUT} = 15A; T_j = -40 to 150°C			10	
V_f	High side free-wheeling diode forward voltage	I_f = 15A		0.8	1.1	V
$I_{L(off)}$	High side off state output current (per channel)	T_j = 25°C; V_{OUTX} = EN_X = 0V; V_{CC} = 13V			3	µA
		T_j = 125°C; V_{OUTX} = EN_X = 0V; V_{CC} = 13V			5	
I_{RM}	Dynamic cross-conduction current	I_{OUT} = 15A (see *Figure 7*)		0.7		A

Table 7. Logic inputs (IN_A, IN_B, EN_A, EN_B)

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
V_{IL}	Input low level voltage	Normal operation ($DIAG_X$/EN_X pin acts as an input pin)			1.25	V
V_{IH}	Input high level voltage		3.25			
V_{IHYST}	Input hysteresis voltage		0.5			
V_{ICL}	Input clamp voltage	I_{IN} = 1mA	5.5	6.3	7.5	
		I_{IN} = -1mA	-1.0	-0.7	-0.3	
I_{INL}	Input low current	V_{IN} = 1.25V	1			µA
I_{INH}	Input high current	V_{IN} = 3.25V			10	
V_{DIAG}	Enable output low level voltage	Fault operation ($DIAG_X$/EN_X pin acts as an output pin); I_{EN} = 1mA			0.4	V

Table 8. PWM

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
V_{pwl}	PWM low level voltage				1.25	V
I_{pwl}	PWM pin current	V_{pw} = 1.25V	1			µA
V_{pwh}	PWM high level voltage		3.25			V
I_{pwh}	PWM pin current	V_{pw} = 3.25V			10	µA
$V_{pwhhyst}$	PWM hysteresis voltage		0.5			V
V_{pwcl}	PWM clamp voltage	I_{pw} = 1mA	V_{CC} + 0.3	V_{CC} + 0.7	V_{CC} + 1.0	
		I_{pw} = -1mA	-6.0	-4.5	-3.0	
C_{INPWM}	PWM pin input capacitance	V_{IN} = 2.5V			25	pF

Table 9. Switching (V_{CC} = 13V, R_{LOAD} = 0.87Ω , unless otherwise specified)

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
f	PWM frequency		0		20	kHz
$t_{d(on)}$	Turn-on delay time	Input rise time < 1µs (see *Figure 6*)			250	µs
$t_{d(off)}$	Turn-off delay time	Input rise time < 1µs (see *Figure 6*)			250	
t_r	Rise time	(see *Figure 5*)		1	1.6	
t_f	Fall time	(see *Figure 5*)		1.2	2.4	
t_{DEL}	Delay time during change of operating mode	(see *Figure 4*)	300	600	1800	
t_{rr}	High side free wheeling diode reverse recovery time	(see *Figure 7*)		110		ns
$t_{off(min)}$ (1)	PWM minimum off time	9V < V_{CC} < 16V; T_j = 25°C; L = 250µH; I_{OUT} = 15A			6	µs

1. To avoid false Short to Battery detection during PWM operation, the PWM signal must be low for a time longer than 6µs.

Table 10. Protection and diagnostic

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
V_{USD}	Undervoltage shut-down				5.5	V
	Undervoltage reset			4.7		
V_{OV}	Overvoltage shut-down		16	19	22	
I_{LIM}	High side current limitation		30	50	70	A
V_{CLP}	Total clamp voltage (V_{CC} to GND)	I_{OUT} = 15A	43	48	54	V
T_{TSD}	Thermal shut-down temperature	V_{IN} = 3.25V	150	175	200	°C
T_{TR}	Thermal reset temperature		135			
T_{HYST}	Thermal hysteresis		7	15		

Table 11. Current sense (9V < V_{CC} < 16V)

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
K_1	I_{OUT}/I_{SENSE}	I_{OUT} = 30A; R_{SENSE} = 1.5kΩ; T_j = -40 to 150°C	9665	11370	13075	
K_2	I_{OUT}/I_{SENSE}	I_{OUT} = 8A; R_{SENSE} = 1.5kΩ; T_j = -40 to 150°C	9096	11370	13644	
dK_1 / K_1 (1)	Analog sense current drift	I_{OUT} = 30A; R_{SENSE} = 1.5kΩ; T_j = -40 to 150°C	-8		+8	%
dK_2 / K_2 (1)	Analog sense current drift	I_{OUT} > 8A; R_{SENSE} = 1.5kΩ; T_j = -40 to 150°C	-10		+10	
I_{SENSEO}	Analog sense leakage current	I_{OUT} = 0A; V_{SENSE} = 0V; T_j = -40 to 150°C	0		65	µA

1. Analog sense current drift is deviation of factor K for a given device over (-40°C to 150°C and 9V < V_{CC} < 16V) with respect to its value measured at T_j = 25°C, V_{CC} = 13V.

Figure 4. Definition of the delay times measurement

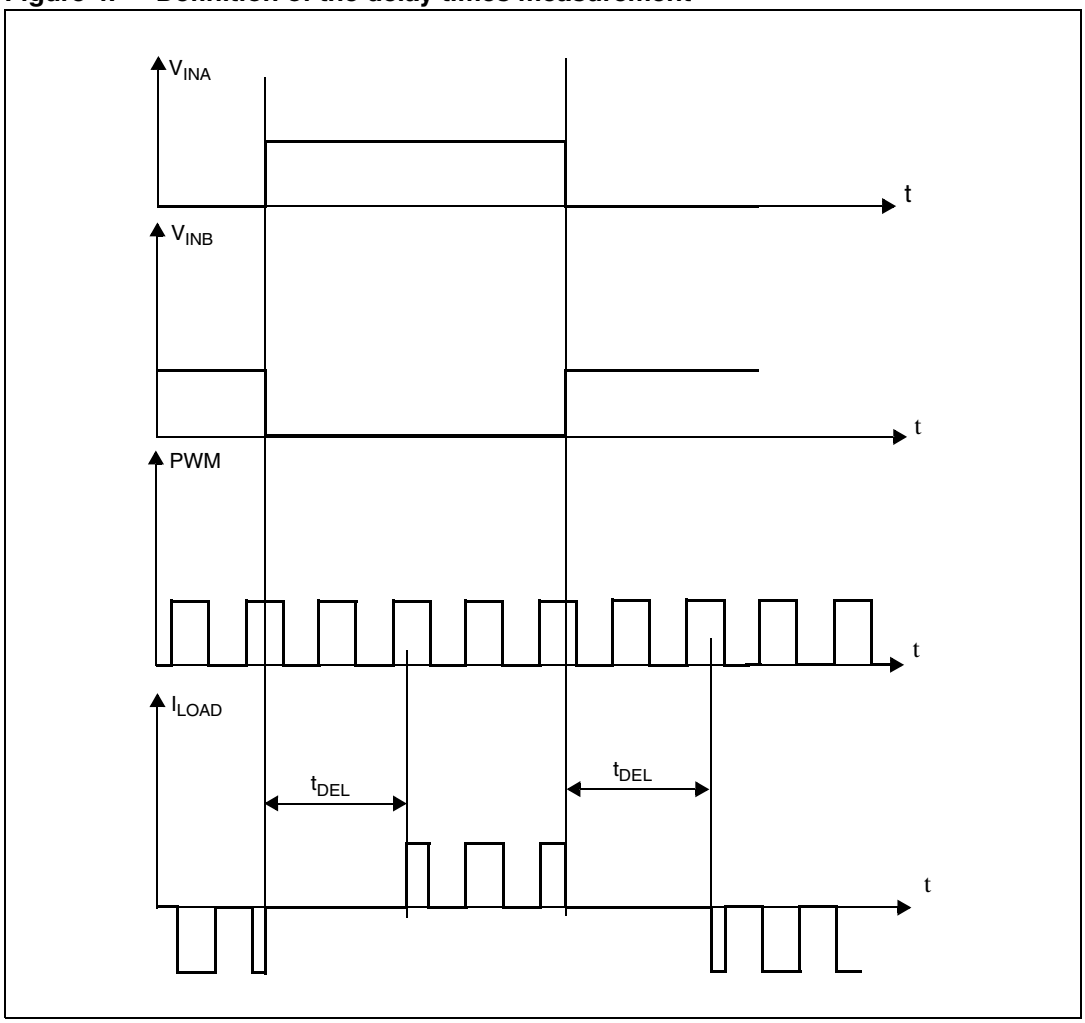


Figure 5. Definition of the low side switching times

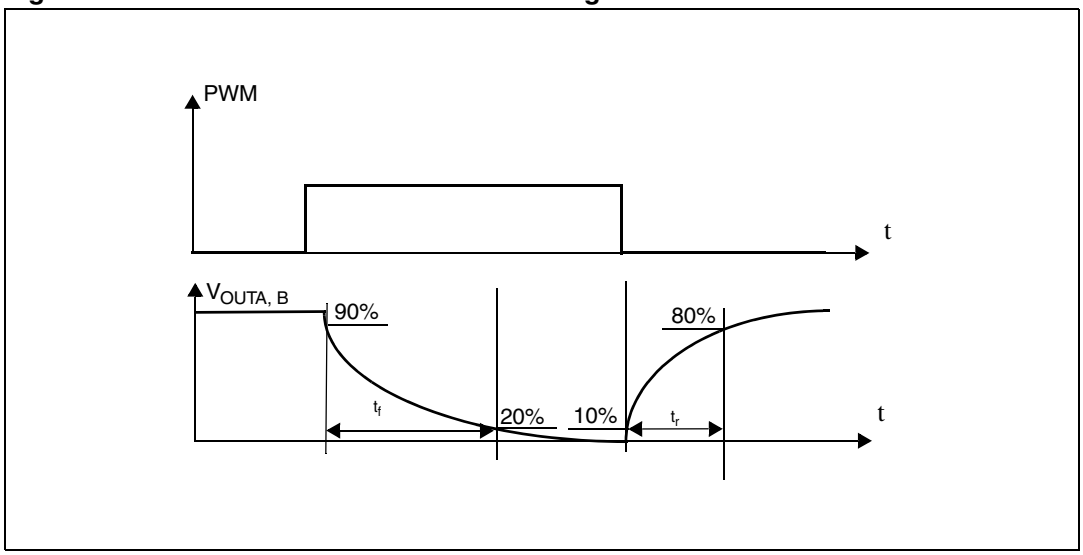


Figure 6. Definition of the high side switching times

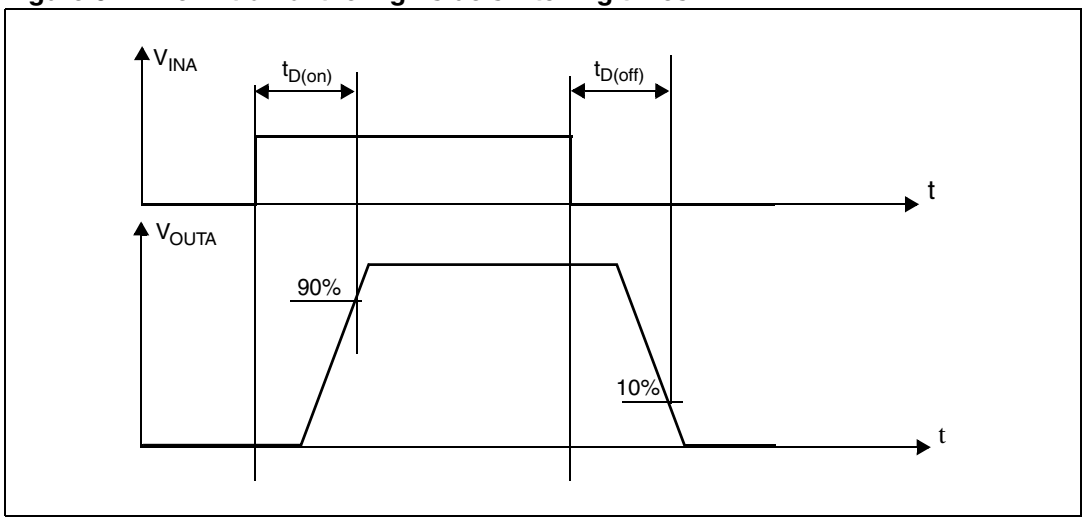


Figure 7. Definition of dynamic cross conduction current during a PWM operation

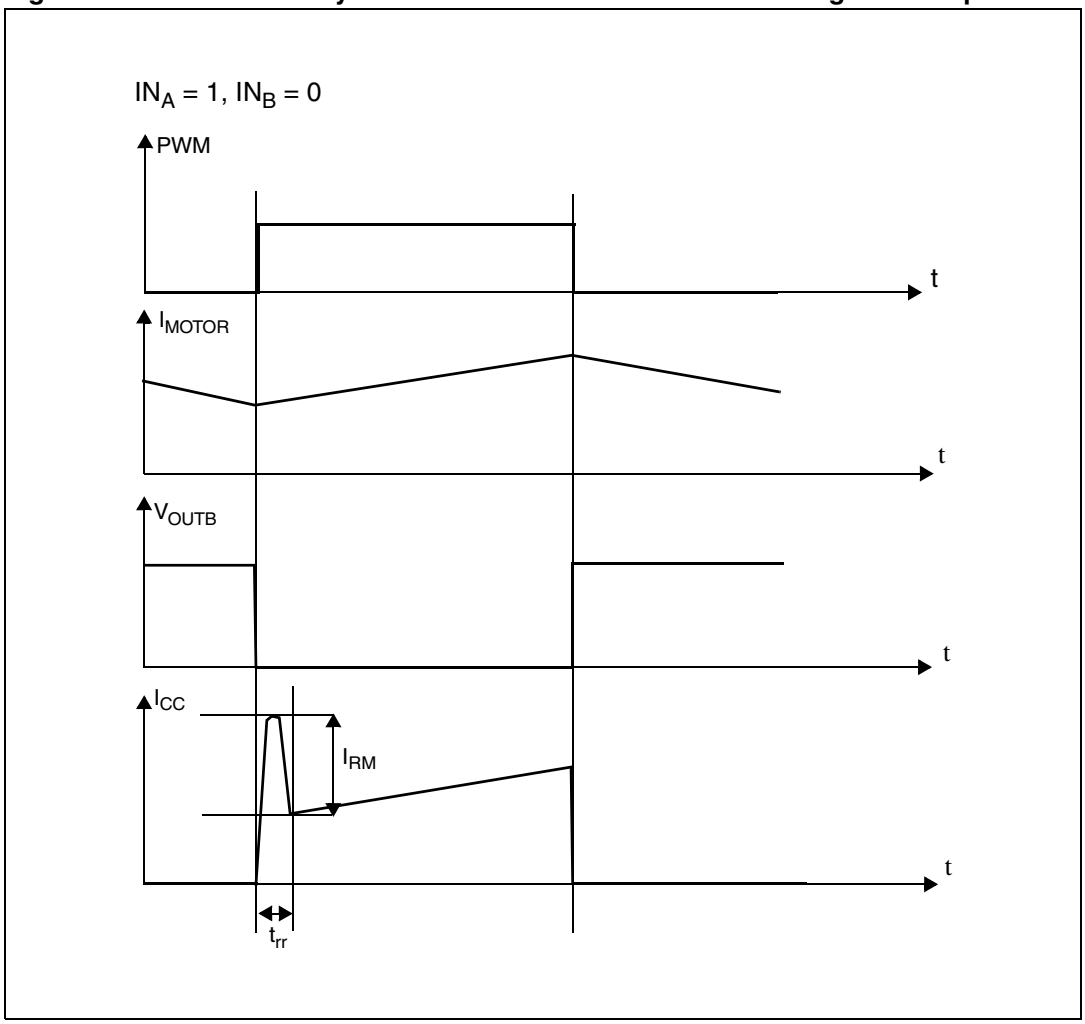


Table 12. Truth table in normal operating conditions

IN_A	IN_B	$DIAG_A/EN_A$	$DIAG_B/EN_B$	OUT_A	OUT_B	CS	Operating mode
1	1	1	1	H	H	High Imp.	Brake to V_{CC}
	0				L	$I_{SENSE} = I_{OUT}/K$	Clockwise (CW)
0	1			L	H		Counterclockwise (CCW)
	0				L	High Imp.	Brake to GND

Table 13. Truth table in fault conditions (detected on OUT_A)

IN_A	IN_B	$DIAG_A/EN_A$	$DIAG_B/EN_B$	OUT_A	OUT_B	CS
1	1	0	1	OPEN	H	High Imp.
	0				L	
0	1				H	I_{OUTB}/K
	0				L	High Imp.
X	X		0		OPEN	
	1		1		H	I_{OUTB}/K
	0				L	High Imp.
		↑ Fault Information		↑ Protection Action		

Note: Notice that saturation detection on the low side power MOSFET is possible only if the impedance of the short-circuit from the output to the battery is less than 100mΩ when the device is supplied with a battery voltage of 13.5V.

Table 14. Electrical transient requirements

ISO T/R - 7637/1 Test pulse	Test Level I	Test Level II	Test Level III	Test Level IV	Test levels delays and impedance
1	-25V	-50V	-75V	-100V	2ms, 10Ω
2	+25V	+50V	+75V	+100V	0.2ms, 10Ω
3a	-25V	-50V	-100V	-150V	0.1µs, 50Ω
3b	+25V	+50V	+75V	+100V	
4	-4V	-5V	-6V	-7V	100ms, 0.01Ω
5	+26.5V	+46.5V	+66.5V	+86.5V	400ms, 2Ω

ISO T/R - 7637/1 test pulse	Test levels result I	Test levels result II	Test levels result III	Test levels result IV
1	C	C	C	C
2				
3a				
3b				
4				
5(1)		E	E	E

1. For load dump exceeding the above value a centralized suppressor must be adopted.

Class	Contents
C	All functions of the device are performed as designed after exposure to disturbance.
E	One or more functions of the device are not performed as designed after exposure to disturbance and cannot be returned to proper operation without replacing the device.

2.3 Electrical characteristics curves

Figure 8. On state supply current

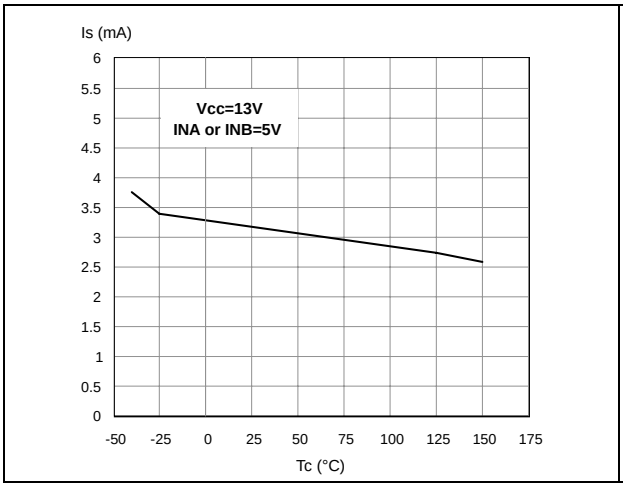


Figure 9. Off state supply current

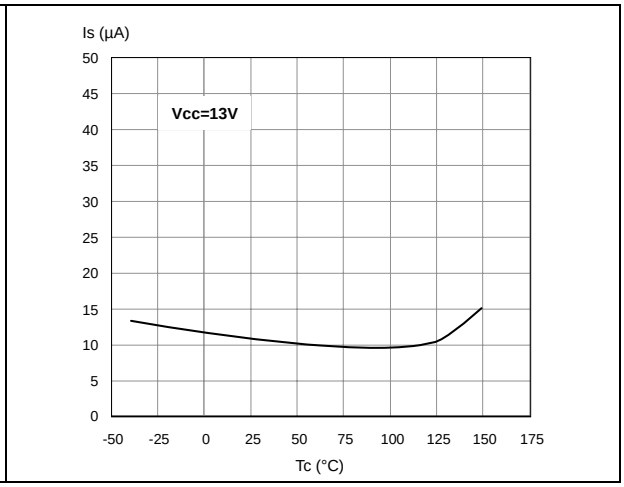


Figure 10. High level input current

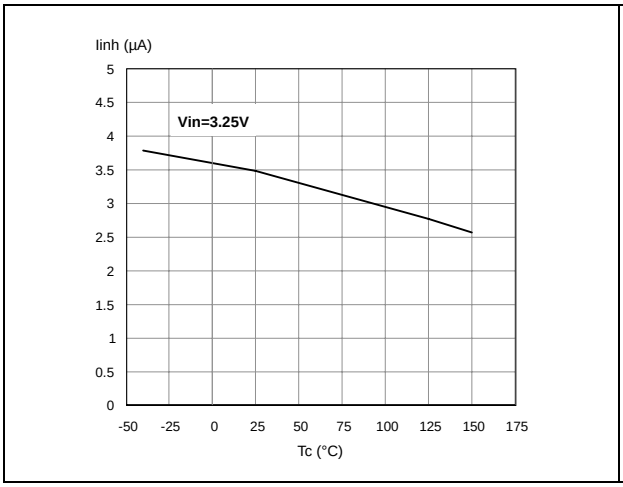


Figure 11. Input clamp voltage

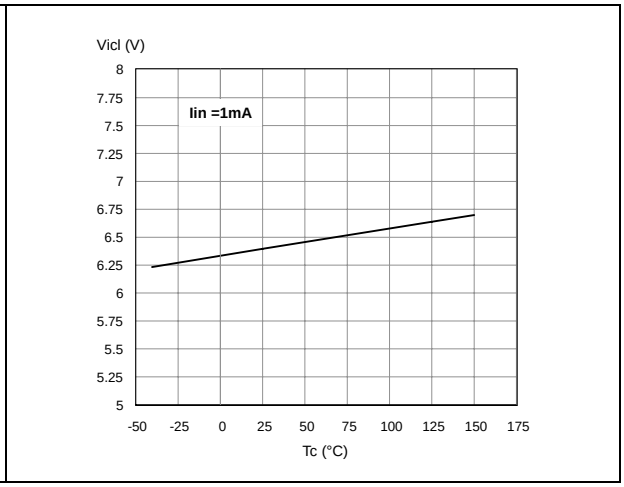


Figure 12. Input high level voltage

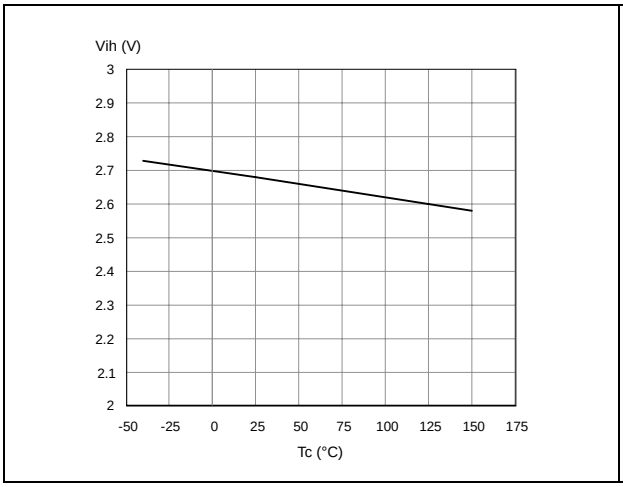


Figure 13. Input low level voltage

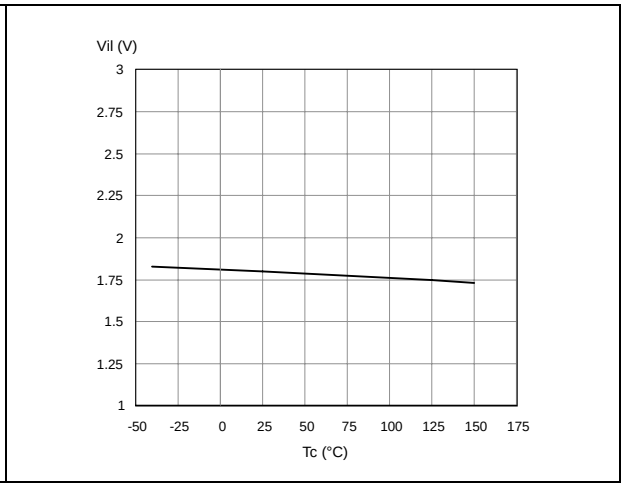


Figure 14. Input hysteresis voltage

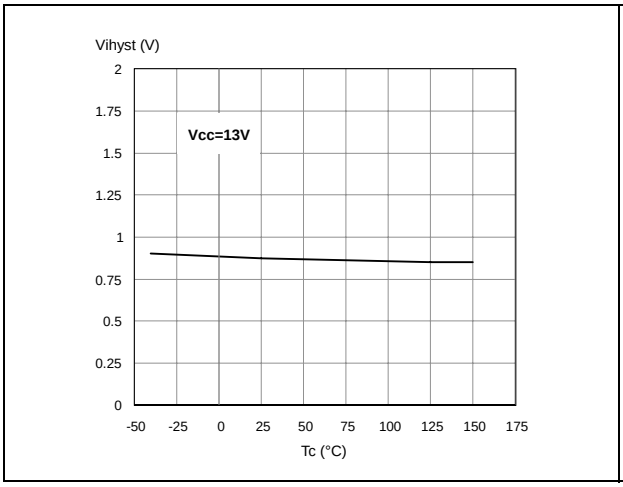


Figure 15. High level enable pin current

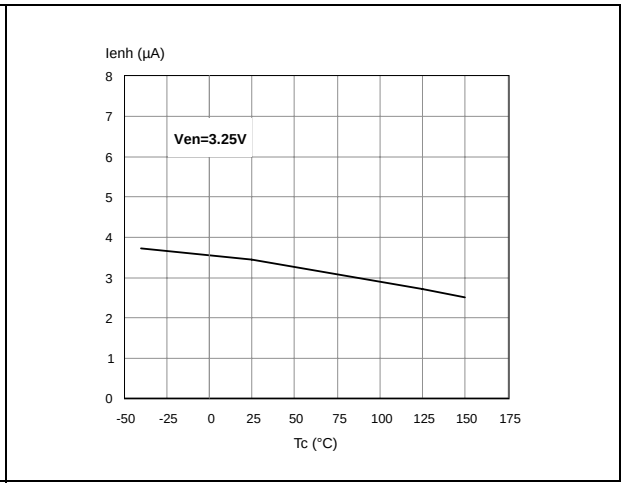


Figure 16. Delay time during change of operation mode

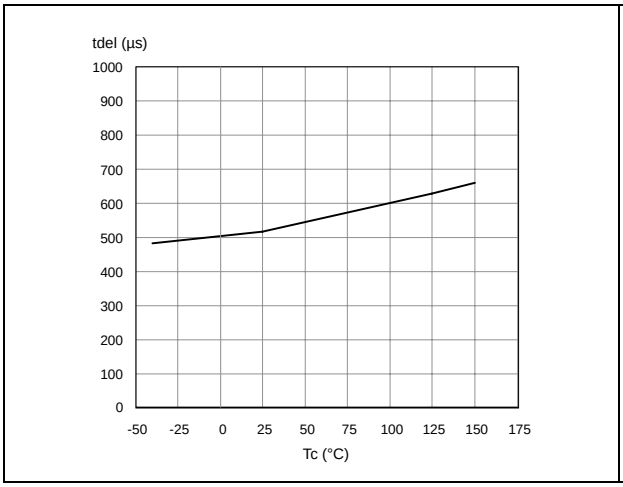


Figure 17. Enable clamp voltage

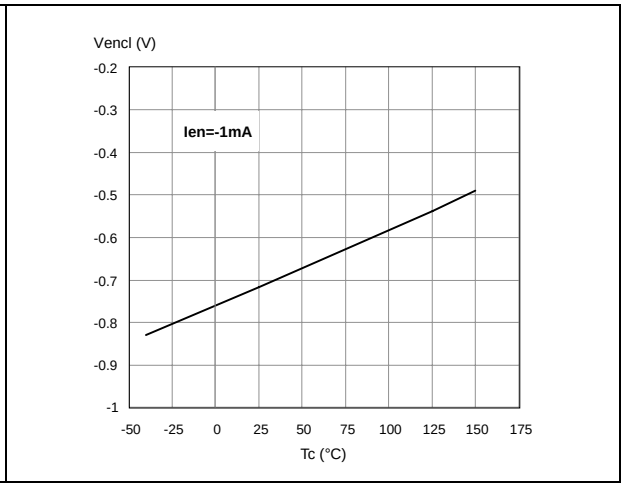


Figure 18. High level enable voltage

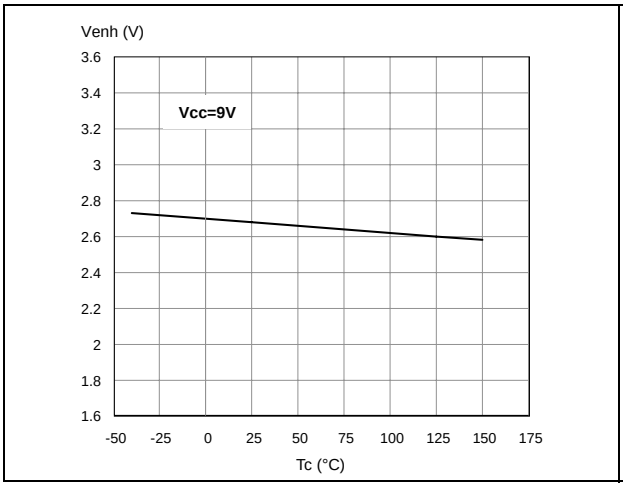


Figure 19. Low level enable voltage

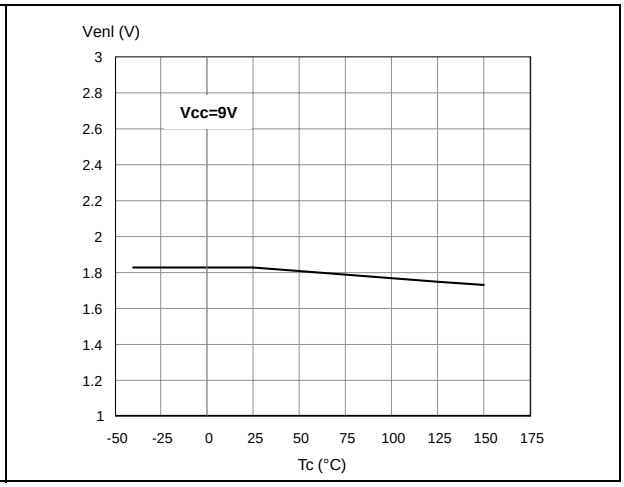


Figure 20. PWM high level voltage

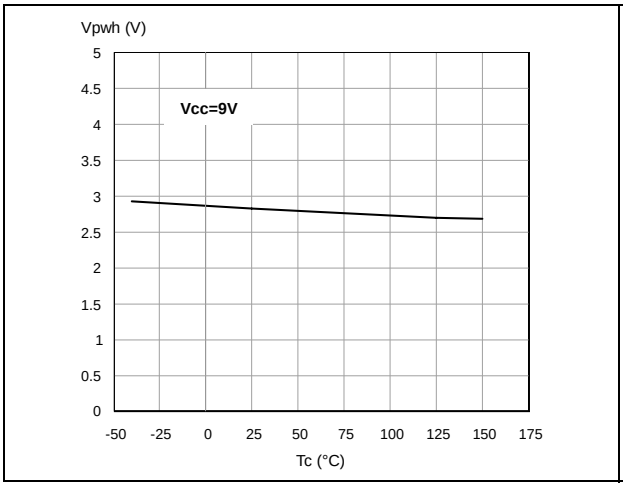


Figure 21. PWM low level voltage

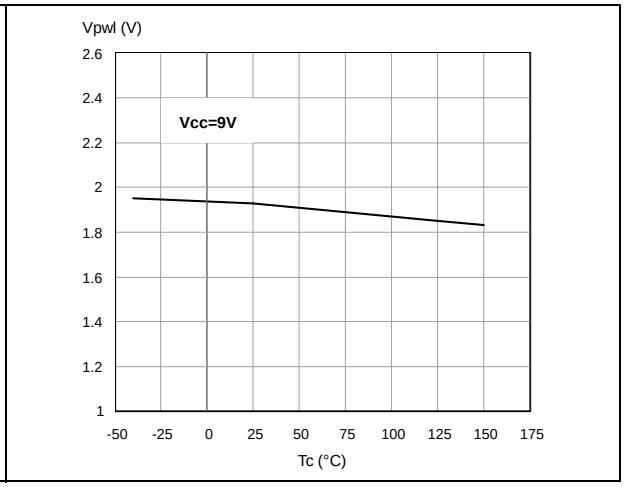


Figure 22. PWM high level current

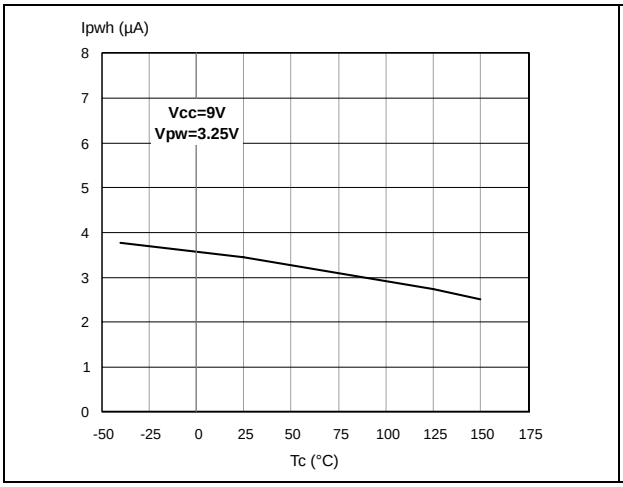


Figure 23. Overvoltage shutdown

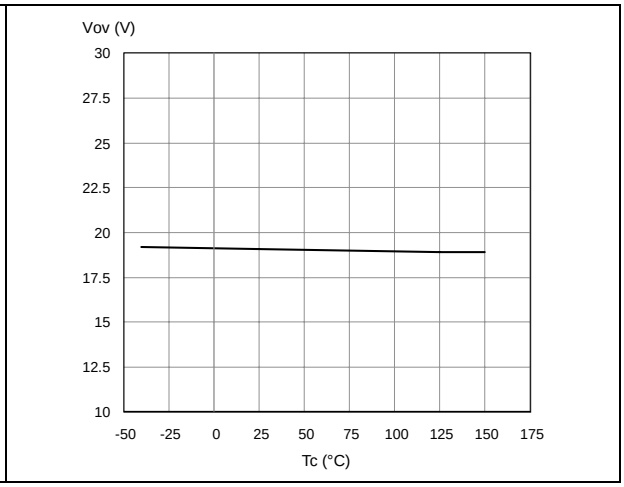


Figure 24. Undervoltage shutdown

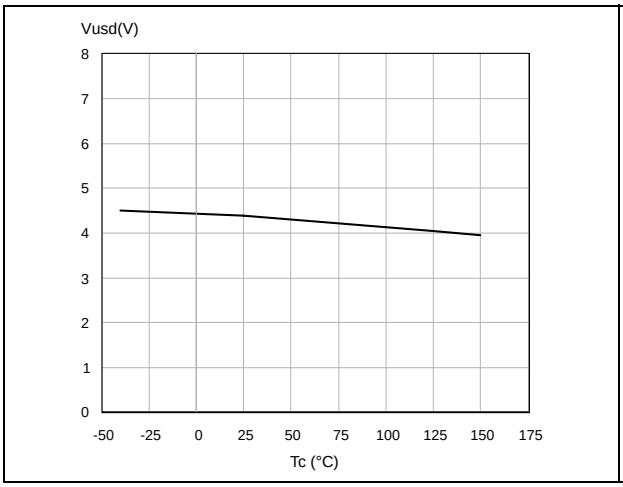


Figure 25. Current limitation

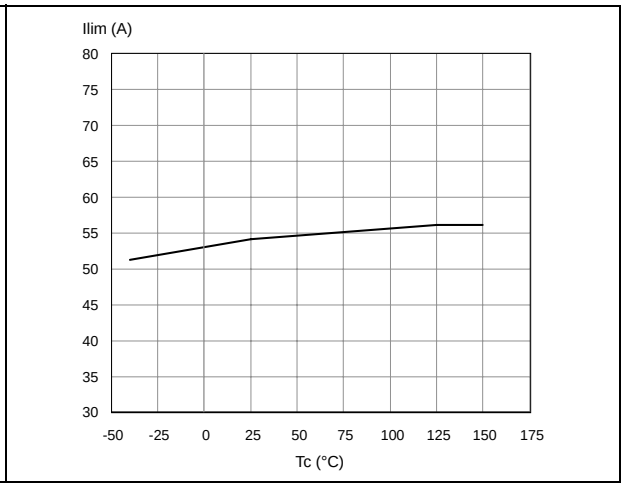


Figure 26. On state high side resistance vs T_{case}

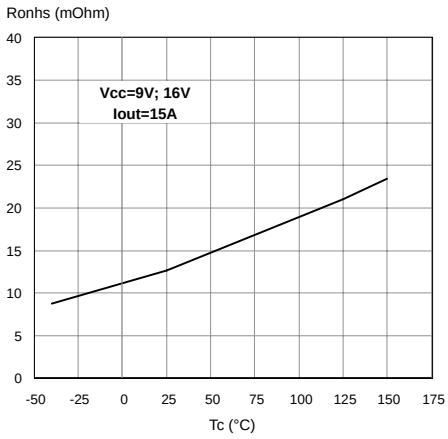


Figure 27. On state low side resistance vs T_{case}

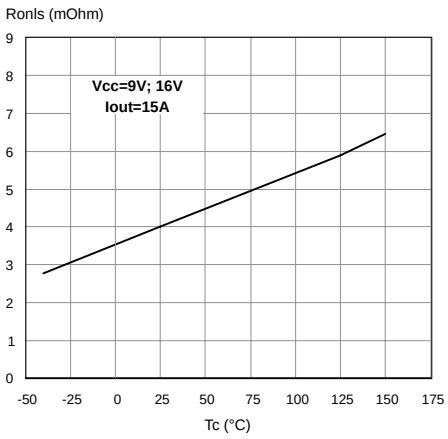


Figure 28. Turn-On delay time

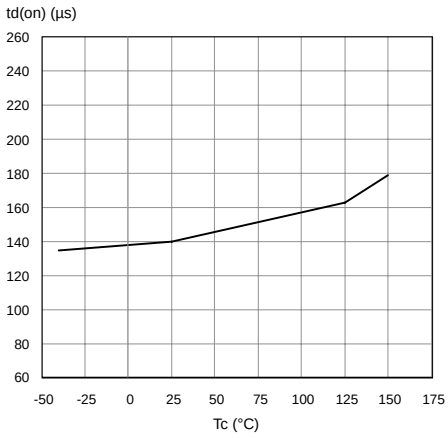


Figure 29. Turn-Off delay time

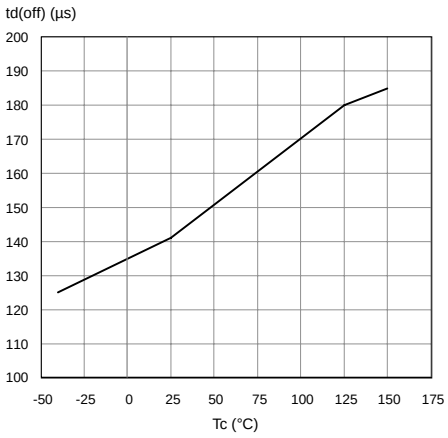


Figure 30. Output voltage rise time

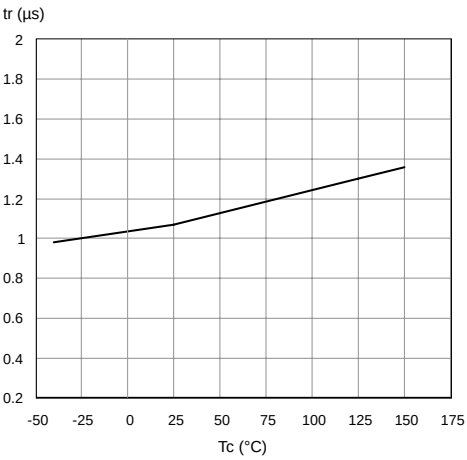
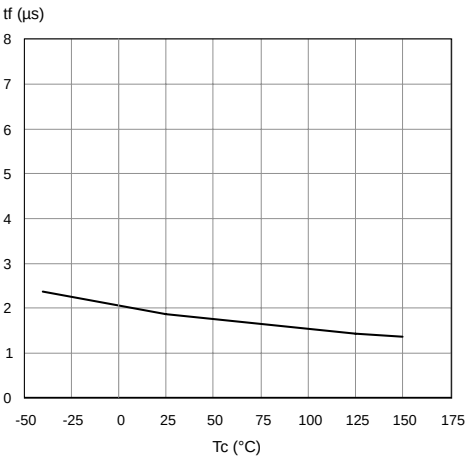


Figure 31. Output voltage fall time

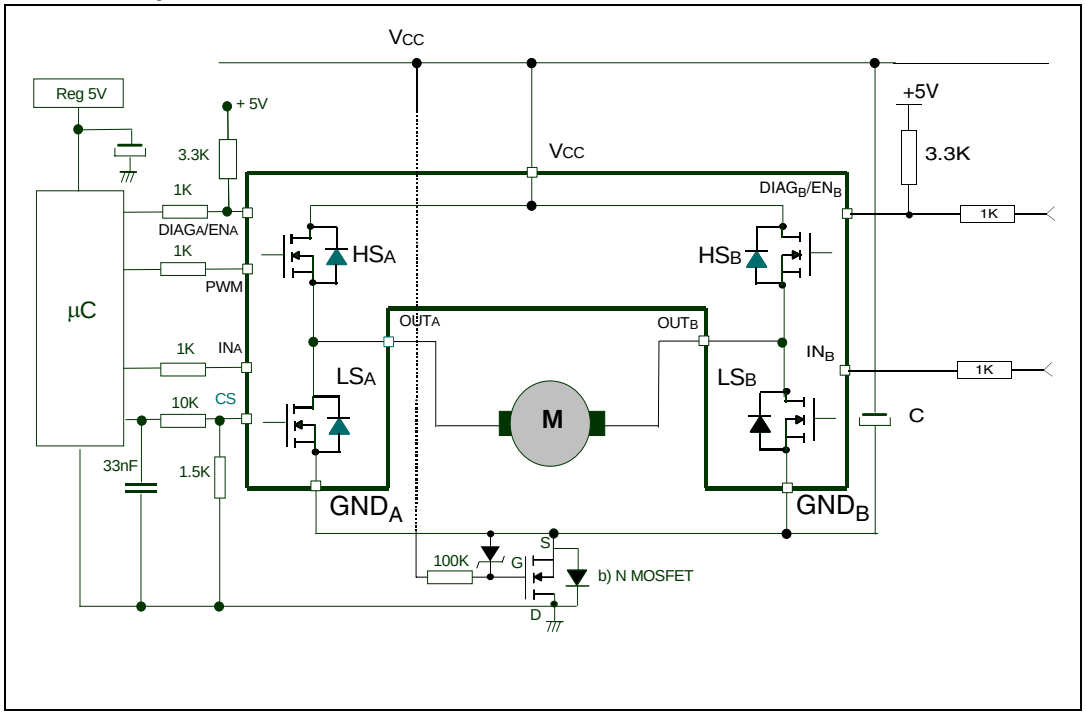


3 Application information

In normal operating conditions the $DIAG_X/EN_X$ pin is considered as an input pin by the device. This pin must be externally pulled high.

PWM pin usage: in all cases, a “0” on the PWM pin will turn off both LS_A and LS_B switches. When PWM rises back to “1”, LS_A or LS_B turn on again depending on the input pin state.

Figure 32. Typical application circuit for DC to 20 kHz PWM operation short circuit protection



Note: The value of the blocking capacitor (C) depends on the application conditions and defines voltage and current ripple onto supply line at PWM operation. Stored energy of the motor inductance may fly back into the blocking capacitor, if the bridge driver goes into tri-state. This causes a hazardous overvoltage if the capacitor is not big enough. As basic orientation, 500µF per 10A load current is recommended.

In case of a fault condition the $DIAG_X/EN_X$ pin is considered as an output pin by the device.The fault conditions are:

- overtemperature on one or both high sides
- short to battery condition on the output (saturation detection on the low side power MOSFET)

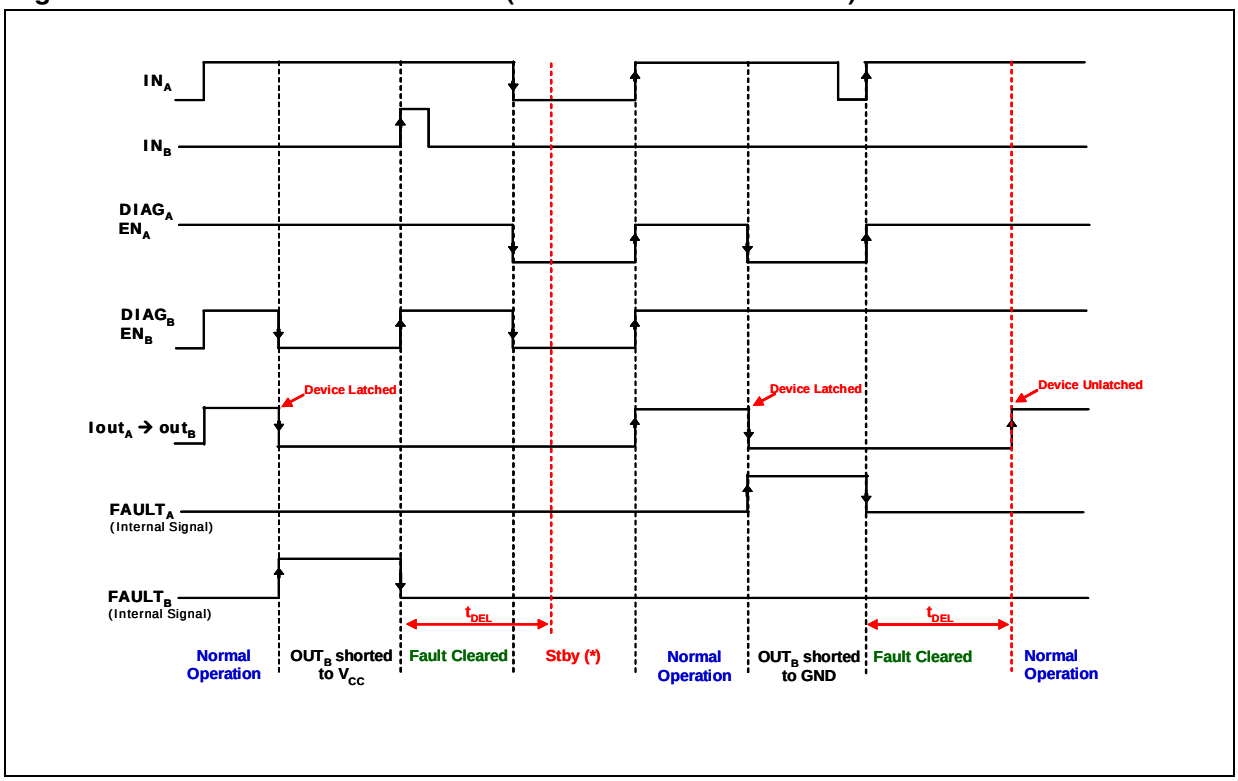
Possible origins of fault conditions may be:

- OUT_A is shorted to ground → overtemperature detection on high side A.
- OUT_A is shorted to V_{CC} → low side power MOSFET saturation detection.

When a fault condition is detected, the user can know which power element is in fault by monitoring the IN_A, IN_B, $DIAG_A/EN_A$ and $DIAG_B/EN_B$ pins.

In any case, when a fault is detected, the faulty leg of the bridge is latched off. To turn on the respective output (OUT_X) again, the input signal must rise from low to high level.

Figure 33. Behavior in fault condition (How a fault can be cleared)



Note: In case of the fault condition is not removed, the procedure for unlatching and sending the device in Stby mode is:

- Clear the fault in the device (toggle : INA if ENA=0 or INB if ENB=0)

- Pull low all inputs, PWM and Diag/EN pins within tDEL.

If the Diag/En pins are already low, PWM=0, the fault can be cleared simply toggling the input. The device will enter in stby mode as soon as the fault is cleared.

3.1 Reverse battery protection

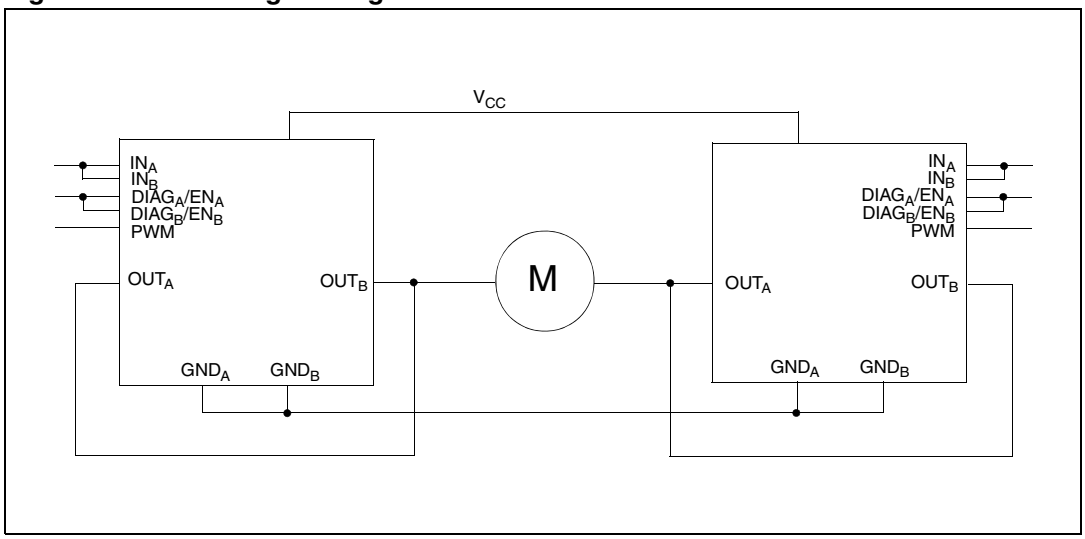
Three possible solutions can be considered:

1. a Schottky diode D connected to V_{CC} pin
2. an N-channel MOSFET connected to the GND pin (see *Figure 32: Typical application circuit for DC to 20 kHz PWM operation short circuit protection on page 20*)
3. a P-channel MOSFET connected to the V_{CC} pin

The device sustains no more than -30A in reverse battery conditions because of the two body diodes of the power MOSFETs. Additionally, in reverse battery condition the I/Os of VNH2SP30-E are pulled down to the V_{CC} line (approximately -1.5V). A series resistor must

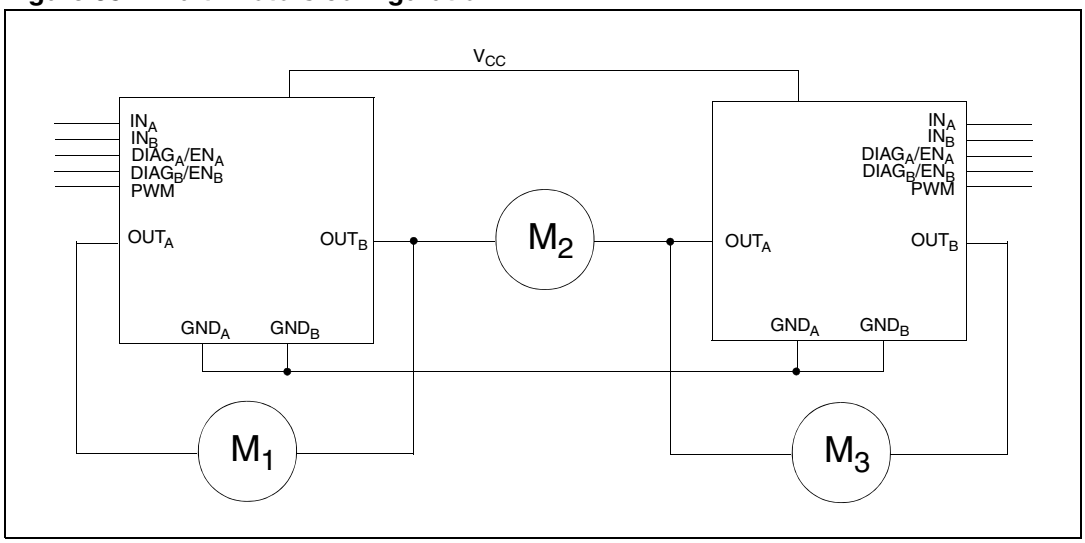
be inserted to limit the current sunk from the microcontroller I/Os. If I_{Rmax} is the maximum target reverse current through µC I/Os, the series resistor is:

Figure 34. Half-bridge configuration



Note: The VNH2SP30-E can be used as a high power half-bridge driver achieving an On resistance per leg of 9.5mΩ.

Figure 35. Multi-motors configuration



Note: The VNH2SP30-E can easily be designed in multi-motors driving applications such as seat positioning systems where only one motor must be driven at a time. $DIAG_X/EN_X$ pins allow to put unused half-bridges in high impedance.

Figure 36. Waveforms in full bridge operation

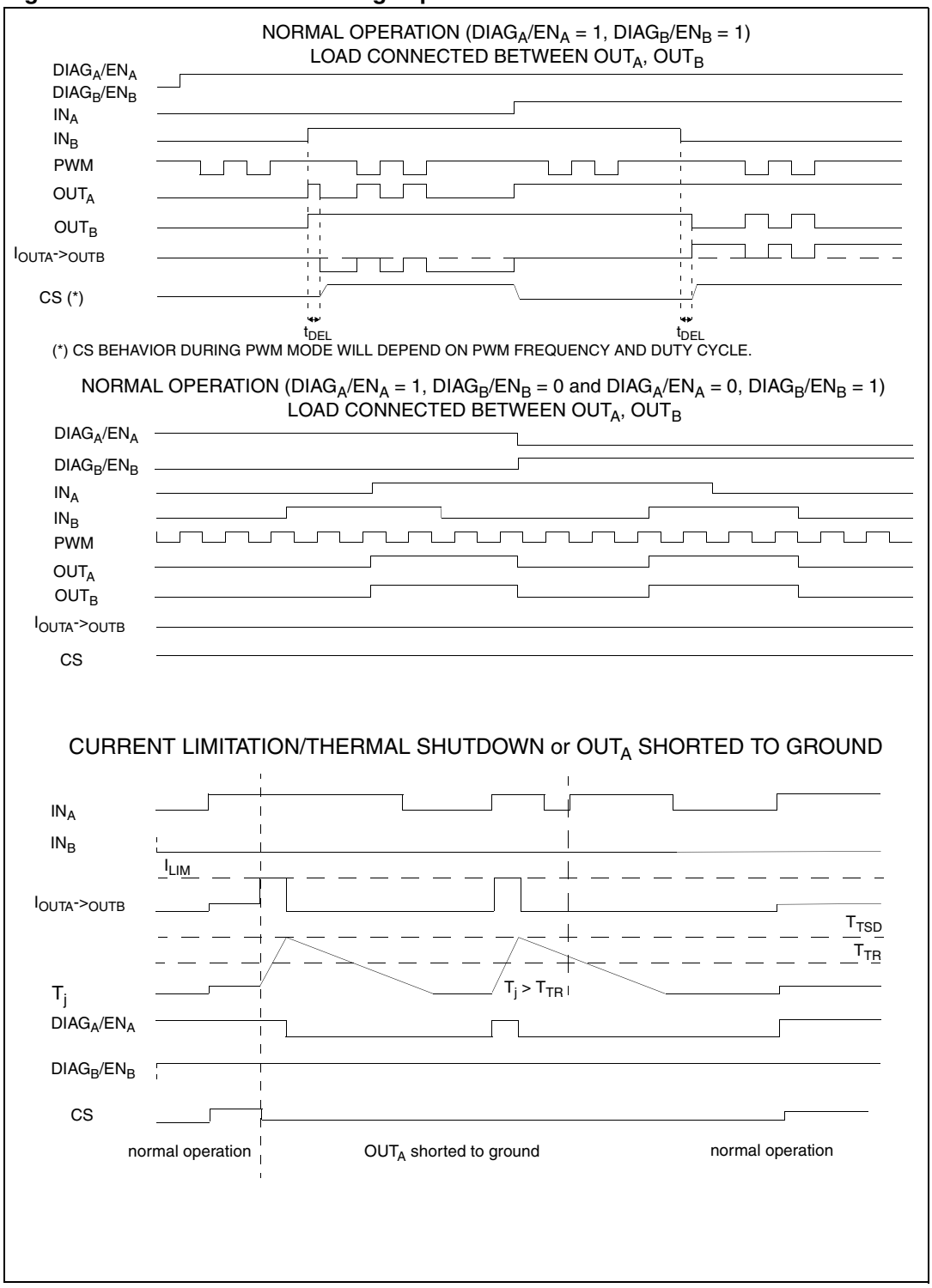
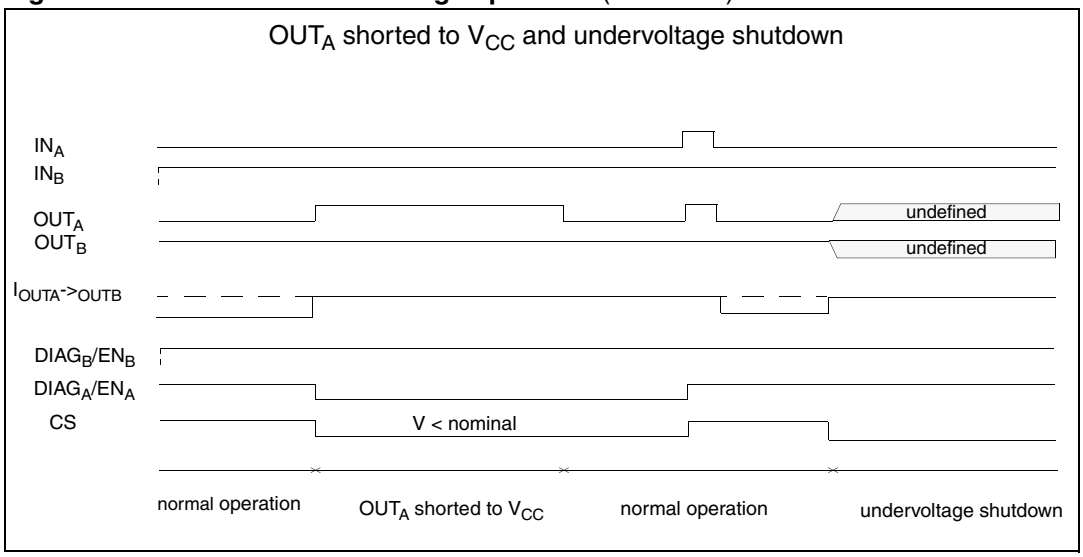


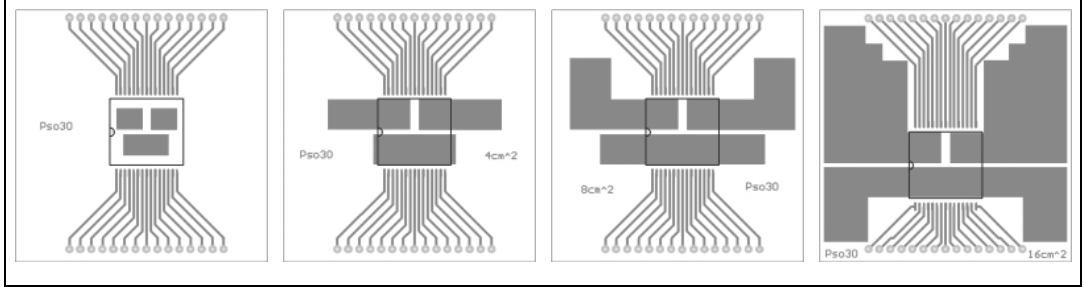
Figure 37. Waveforms in full bridge operation (continued)



4 Package and PCB thermal data

4.1 PowerSSO-30 thermal data

Figure 38. MultiPowerSO-30™ PC board



Note: Layout condition of R_{th} and Z_{th} measurements (PCB FR4 area = 58mm x 58mm, PCB thickness = 2mm. Cu thickness = 35µm, Copper areas: from minimum pad layout to 16cm^2).

Figure 39. Chipset configuration

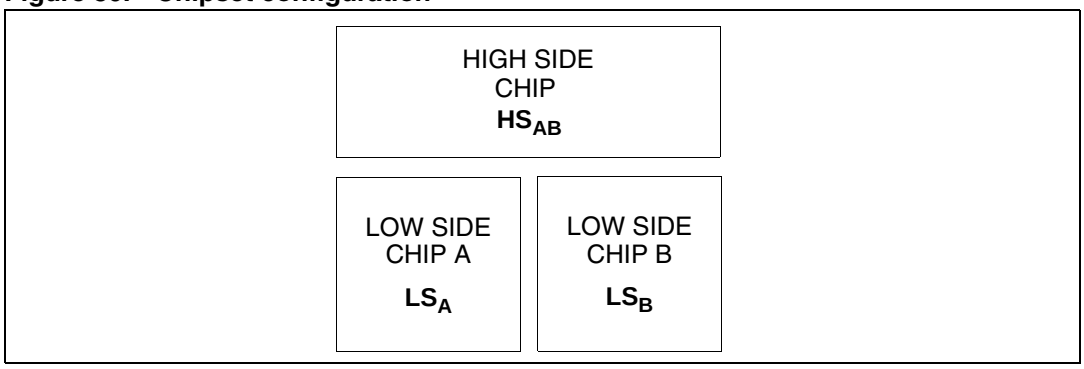
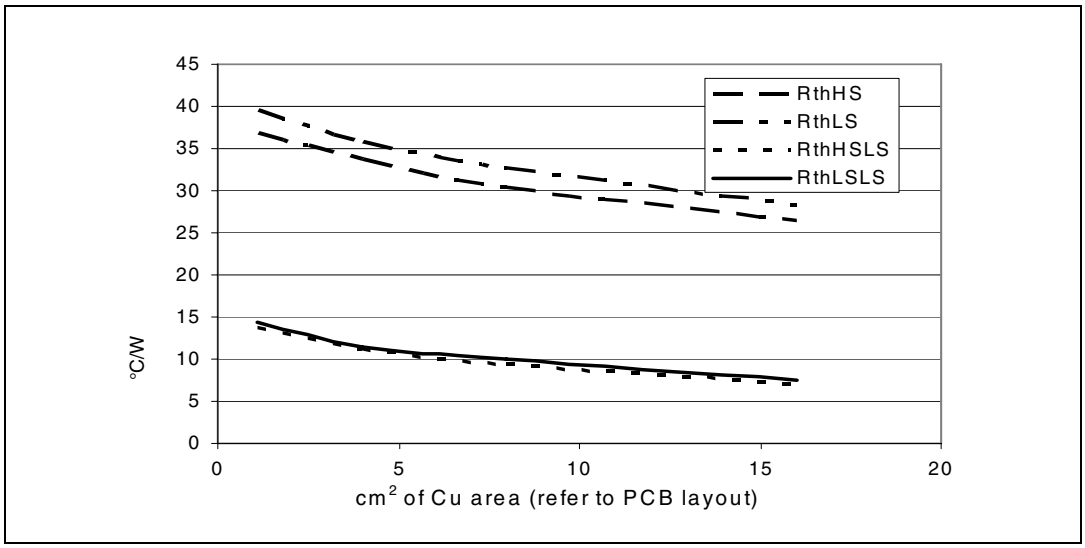


Figure 40. Auto and mutual $R_{thj\text{-}amb}$ vs PCB copper area in open box free air condition



4.1.1 Thermal calculation in clockwise and anti-clockwise operation in steady-state mode

Table 15. Thermal calculation in clockwise and anti-clockwise operation in steady-state mode

HS_A	HS_B	LS_A	LS_B	T_{jHSAB}	T_{jLSA}	T_{jLSB}
ON	OFF	OFF	ON	$P_{dHSA} \times R_{thHS} + P_{dLSB} \times R_{thHSLS} + T_{amb}$	$P_{dHSA} \times R_{thHSLS} + P_{dLSB} \times R_{thLSLS} + T_{amb}$	$P_{dHSA} \times R_{thHSLS} + P_{dLSB} \times R_{thLS} + T_{amb}$
OFF	ON	ON	OFF	$P_{dHSB} \times R_{thHS} + P_{dLSA} \times R_{thHSLS} + T_{amb}$	$P_{dHSB} \times R_{thHSLS} + P_{dLSA} \times R_{thLS} + T_{amb}$	$P_{dHSB} \times R_{thHSLS} + P_{dLSA} \times R_{thLSLS} + T_{amb}$

4.1.2 Thermal resistances definition (values according to the PCB heatsink area)

R_{thHS} = R_{thHSA} = R_{thHSB} = High Side Chip Thermal Resistance Junction to Ambient (HS_A or HS_B in ON state)

R_{thLS} = R_{thLSA} = R_{thLSB} = Low Side Chip Thermal Resistance Junction to Ambient

R_{thHSLS} = $R_{thHSALSB}$ = $R_{thHSBLSA}$ = Mutual Thermal Resistance Junction to Ambient between High Side and Low Side Chips

R_{thLSLS} = $R_{thLSALSB}$ = Mutual Thermal Resistance Junction to Ambient between Low Side Chips

4.1.3 Thermal calculation in transient mode[(a)]

T_{jHSAB} = $Z_{thHS} \times P_{dHSAB} + Z_{thHSLS} \times (P_{dLSA} + P_{dLSB}) + T_{amb}$

T_{jLSA} = $Z_{thHSLS} \times P_{dHSAB} + Z_{thLS} \times P_{dLSA} + Z_{thLSLS} \times P_{dLSB} + T_{amb}$

T_{jLSB} = $Z_{thHSLS} \times P_{dHSAB} + Z_{thLSLS} \times P_{dLSA} + Z_{thLS} \times P_{dLSB} + T_{amb}$

4.1.4 Single pulse thermal impedance definition (values according to the PCB heatsink area)

Z_{thHS} = High Side Chip Thermal Impedance Junction to Ambient

Z_{thLS} = Z_{thLSA} = Z_{thLSB} = Low Side Chip Thermal Impedance Junction to Ambient

Z_{thHSLS} = $Z_{thHSABLSA}$ = $Z_{thHSABLSB}$ = Mutual Thermal Impedance Junction to Ambient between High Side and Low Side Chips

Z_{thLSLS} = $Z_{thLSALSB}$ = Mutual Thermal Impedance Junction to Ambient between Low Side Chips

a. Calculation is valid in any dynamic operating condition. P_d values set by user.

Equation 1: pulse calculation formula

$$Z_{TH\delta} = R_{TH} \times \delta + Z_{THtp}(1-\delta)$$

where $\delta = t_p / T$

Figure 41. MultiPowerSO-30 HSD thermal impedance junction ambient single pulse

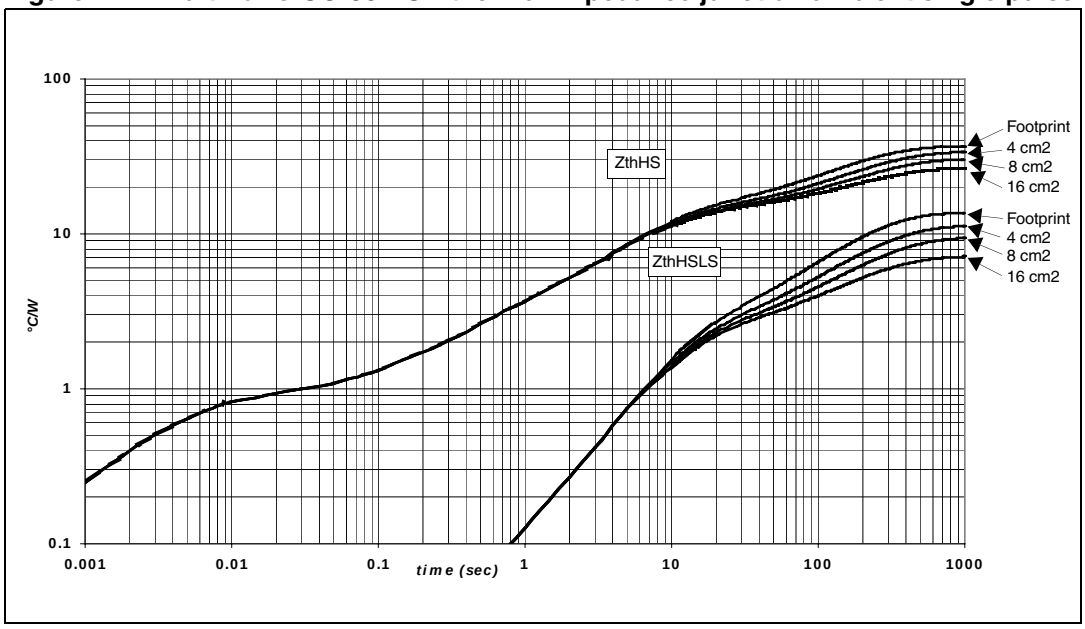


Figure 42. MultiPowerSO-30 LSD thermal impedance junction ambient single pulse

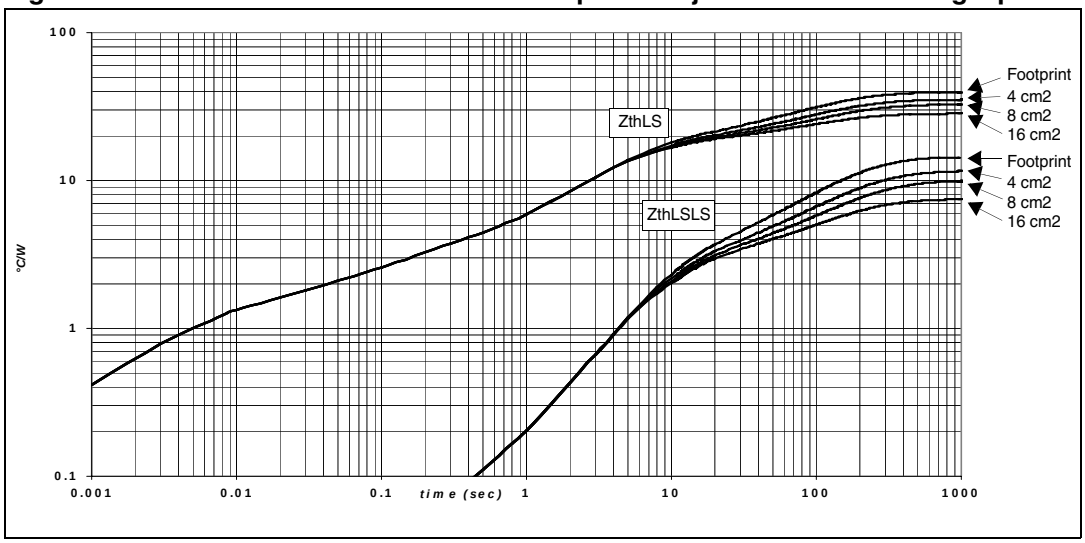


Figure 43. Thermal fitting model of an H-bridge in MultiPowerSO-30

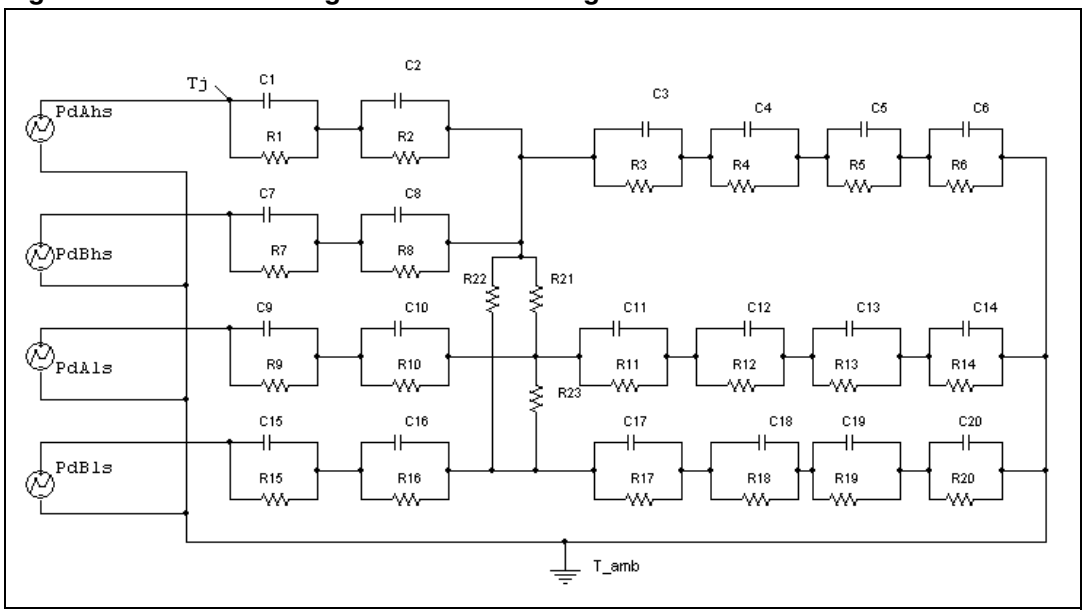


Table 16. Thermal parameters(1)

Area/island (cm^2)	Footprint	4	8	16
R1 = R7 (°C/W)	0.05			
R2 = R8 (°C/W)	0.3			
R3 (°C/W)	0.5			
R4 (°C/W)	1.3			
R5 (°C/W)	14			
R6 (°C/W)	44.7	39.1	31.6	23.7
R9 = R15 (°C/W)	0.2			
R10 = R16 (°C/W)	0.4			
R11 = R17 (°C/W)	0.8			
R12 = R18 (°C/W)	1.5			
R13 = R19 (°C/W)	20			
R14 = R20 (°C/W)	46.9	36.1	30.4	20.8
R21 = R22 = R23 (°C/W)	115			
C1 = C7 (W.s/°C)	0.005			
C2 = C8 (W.s/°C)	0.008			
C3 = C11 = C17 (W.s/°C)	0.01			
C4 = C13 = C19 (W.s/°C)	0.3			
C5 (W.s/°C)	0.6			
C6 (W.s/°C)	5	7	9	11
C9 = C15 (W.s/°C)	0.003			
C10 = C16 (W.s/°C)	0.006			
C12 = C18 (W.s/°C)	0.075			
C14 = C20 (W.s/°C)	2.5	3.5	4.5	5.5

1. The blank space means that the value is the same as the previous one.

5 Package and packing information

5.1 ECOPACK® packages

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. ECOPACK® packages are lead-free. The category of Second Level Interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label.

ECOPACK is an ST trademark. ECOPACK specifications are available at www.st.com.

5.2 MultiPowerSO-30 package mechanical data

Figure 44. MultiPowerSO-30 package outline

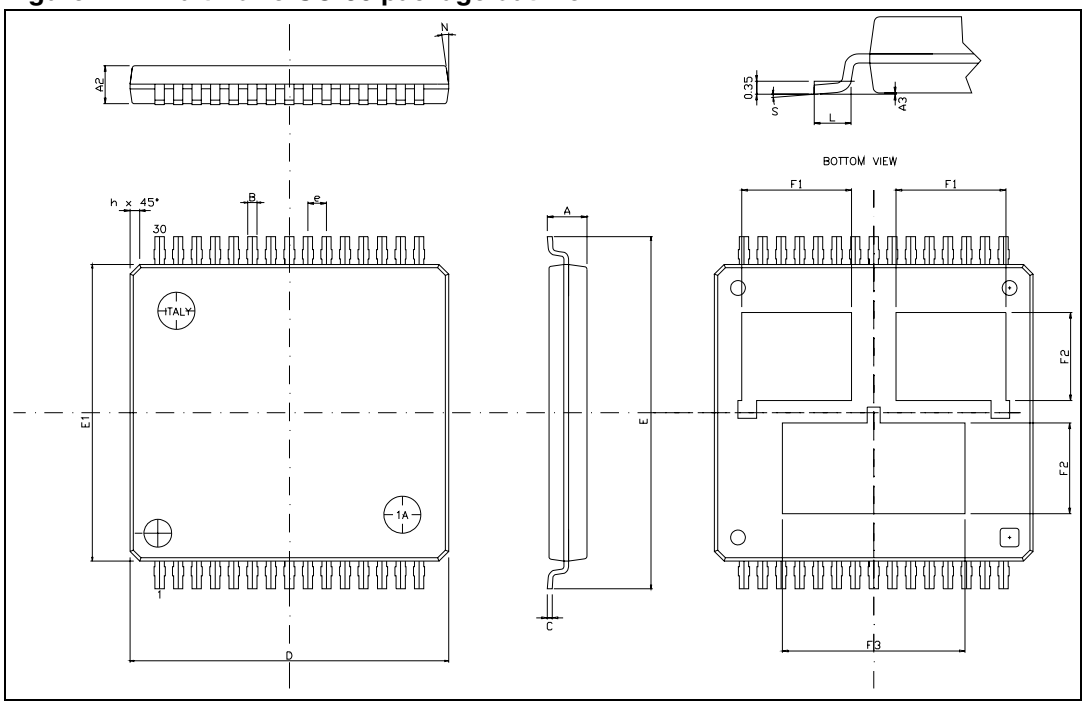
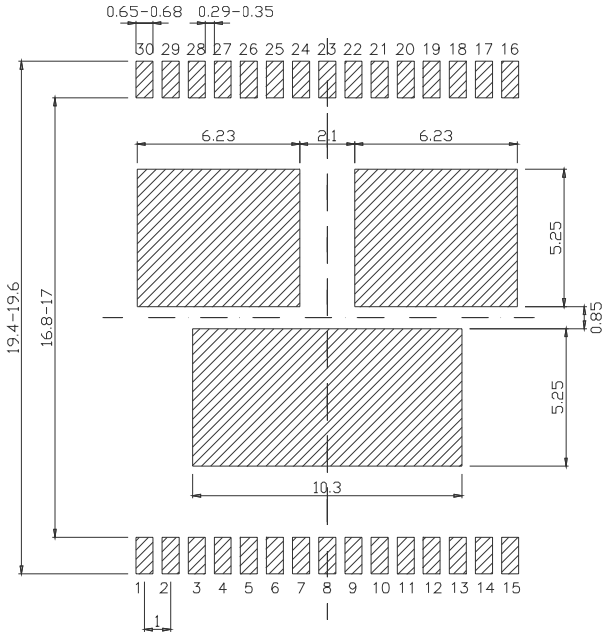


Table 17. MultiPowerSO-30 mechanical data

Symbol	Millimeters		
	Min	Typ	Max
A			2.35
A2	1.85		2.25
A3	0		0.1
B	0.42		0.58
C	0.23		0.32
D	17.1	17.2	17.3
E	18.85		19.15
E1	15.9	16	16.1
e		1	
F1	5.55		6.05
F2	4.6		5.1
F3	9.6		10.1
L	0.8		1.15
N			10deg
S	0deg		7deg

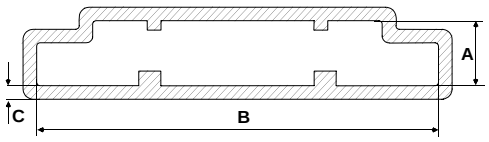
Figure 45. MultiPowerSO-30 suggested pad layout



5.3 Packing information

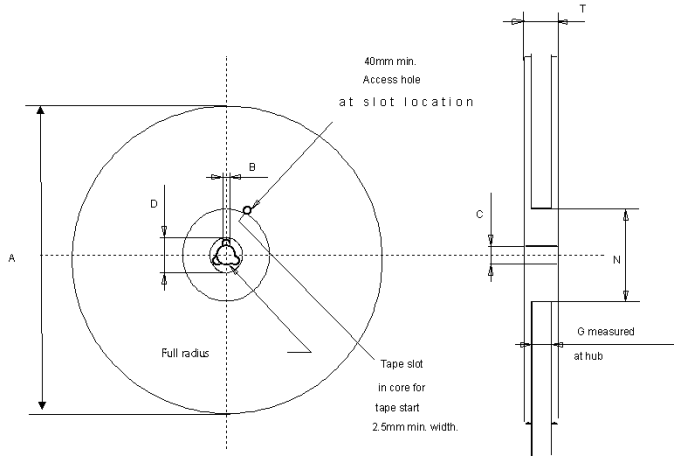
Note: The devices can be packed in tube or tape and reel shipments (see the Device summary on page 1 for packaging quantities).

Figure 46. MultiPowerSO-30 tube shipment (no suffix)



Dimension	mm
Base Q.ty	29
Bulk Q.ty	435
Tube length (± 0.5)	532
A	3.82
B	23.6
C (± 0.13)	0.8

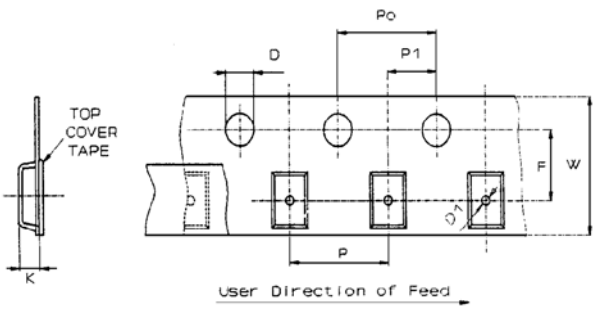
Figure 47. MultiPowerSO-30 tape and reel shipment (suffix "TR")



Reel dimensions

SO-28 tube shipment (no suffix)

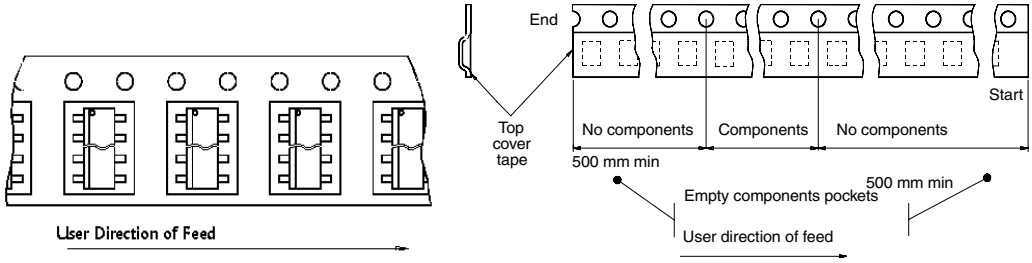
Dimension	mm
Base Q.ty	1000
Bulk Q.ty	1000
A (max)	330
B (min)	1.5
C (± 0.2)	13
D (min)	20.2
G (+ 2 / -0)	32
N (min)	100
T (max)	38.4



Tape dimensions

According to Electronic Industries Association (EIA) Standard 481 rev. A, Feb 1986

Description	Dimension	mm
Tape width	W	32
Tape Hole Spacing	P0 (± 0.1)	4
Component Spacing	P	24
Hole Diameter	D (± 0.1/-0)	1.5
Hole Diameter	D1 (min)	2
Hole Position	F (± 0.1)	14.2
Compartment Depth	K (max)	2.2



6 Revision history

Table 18. Document revision history

Date	Revision	Description of changes
Sep-2004	1	First issue
Dec- 2004	2	Inserted $t_{off(min)}$ test condition modification and note Modified I_{RM} figure number
Feb-2005	3	Minor changes
Apr-2005	4	Public release
01-Sep-2006	5	Document converted into new ST corporate template. Added table of contents, list of tables and list of figures Removed figure number from package outline *on page 1* Changed *Features on page 1* to add ECOPACK® package Added *Section 1: Block diagram and pin description on page 5* Added *Section 2.2: Electrical characteristics on page 9* Added “low” and “high” to parameters for I_{INL} and I_{INH} in *Table 7 on page 9* Inserted note in *Figure 32 on page 20* Added vertical limitation line to left side arrow of $t_{D(off)}$ to *Figure 7 on page 13* Added *Section 4.1: PowerSSO-30 thermal data on page 25* Added *Section 5: Package and packing information on page 29* Added *Section 5.3: Packing information on page 31* Updated disclaimer (last page) to include a mention about the use of ST products in automotive applications
15-May-2007	6	Document reformatted and converted into new ST template.
06-Feb-2008	7	Corrected Heat Slug numbers in *Table 3: Pin definitions and functions*.
02-Oct-2008	8	Added new infomation in *Table 6: Power section* Added *Figure 33: Behavior in fault condition (How a fault can be cleared)*

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